SGUS030E-APRIL 2000-REVISED JULY 2009

## RAD-TOLERANT CLASS-V FLOATING-POINT DIGITAL SIGNAL PROCESSOR

#### **FEATURES**

- Rad-Tolerant: 100-kRad (Si) TID
- SEL Immune at 89MeV-cm2/mg LET Ions
- QML-V Qualified, SMD 5962-98661
- Highest-Performance Floating-Point Digital Signal Processor (DSP) SMJ320C6701
  - 7-ns Instruction Cycle Time
  - 140-MHz Clock Rate
  - Eight 32-Bit Instructions/Cycle
  - Up to One GFLOPS Performance
  - Pin Compatible With 'C6201 Fixed-Point DSP
- SMJ: QML Processing to MIL-PRF-38535
- SM: Standard Processing
- Operating Temperature Ranges
  - 55°C to 115°C
  - 55°C to 125°C
- VelociTI<sup>™</sup> Advanced Very Long Instruction Word (VLIW) 'C67x CPU Core
  - Eight Highly Independent Functional Units:
    - Four ALUs (Floating and Fixed Point)
    - Two ALUs (Fixed Point)
    - Two Multipliers (Floating and Fixed Point)
  - Load-Store Architecture With 32
     32-Bit General-Purpose Registers
  - Instruction Packing Reduces Code Size
  - All Instructions Conditional
- Instruction Set Features
  - Hardware Support for IEEE Single-Precision Instructions
  - Hardware Support for IEEE Double-Precision Instructions
  - Byte Addressable (8-/16-/32-Bit Data)
  - 32-Bit Address Range
  - 8-Bit Overflow Protection
  - Saturation
  - Bit-Field Extract, Set, Clear

- Bit Counting
- Normalization
- 1M-Bit On-Chip SRAM
  - 512K-Bit Internal Program/Cache (16K 32-Bit Instructions)
  - 512K-Bit Dual-Access Internal Data (64K Bytes)
- 32-Bit External Memory Interface (EMIF)
  - Glueless Interface to Synchronous Memories: SDRAM and SBSRAM
  - Glueless Interface to Asynchronous Memories: SRAM and EPROM
- Four-Channel Bootloading
   Direct Memory Access (DMA) Controller With Auxiliary Channel
- 16-Bit Host-Port Interface (HPI)
  - Access to Entire Memory Map
- Two Multichannel Buffered Serial Ports (McBSPs)
  - Direct Interface to T1/E1, MVIP, SCSA Framers
  - ST Bus Switching Compatible
  - Up to 256 Channels Each
  - AC97 Compatible
  - Serial Peripheral Interface (SPI)
     Compatible (Motorola™)
- Two 32-Bit General-Purpose Timers
- Flexible Phase-Locked Loop (PLL) Clock Generator
- IEEE Std 1149.1 (JTAG (1) ) Boundary Scan Compatible
- 429-Pin Ceramic Ball Grid Array (CBGA/GLP) and Ceramic Land Grid Array (CLGA/ZMB) Package Types
- 0.18-μm/5-Level Metal Process
  - CMOS Technology
- 3.3-V I/Os, 1.9 V Internal
- (1) IEEE Std 1149.1-1990 Test Access Port and Boundary Scan Architecture



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

VelociTI, XDS, XDS510, XDS510WS are trademarks of Texas Instruments.

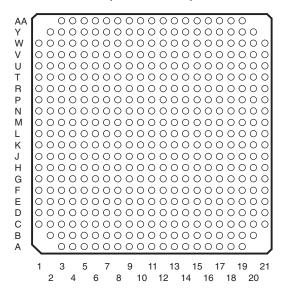
Windows, Win32, NT are trademarks of Microsoft Corporation.

Motorola is a trademark of Motorola, Inc.

SPARC is a trademark of SPARC International. Solaris is a trademark of Sun Microsystems, Inc..



## GLP AND ZMB PACKAGES (BOTTOM VIEW)



#### DESCRIPTION

The SMJ320C67x DSPs are the floating-point DSP family in the SMJ320C6000 platform. The SMJ320C6701 ('C6701) device is based on the high-performance, advanced VelociTI™ very-long-instruction-word (VLIW) architecture developed by Texas Instruments (TI), making this DSP an excellent choice for multichannel and multifunction applications. With performance of up to 1 giga floating-point operations per second (GFLOPS) at a clock rate of 140 MHz, the 'C6701 offers cost-effective solutions to high-performance DSP programming challenges. The 'C6701 DSP possesses the operational flexibility of high-speed controllers and the numerical capability of array processors. This processor has 32 general-purpose registers of 32-bit word length and eight highly independent functional units. The eight functional units provide four floating-/fixed-point ALUs, two fixed-point ALUs, and two floating-/fixed-point multipliers. The 'C6701 can produce two multiply-accumulates (MACs) per cycle for a total of 334 million MACs per second (MMACS). The 'C6701 DSP also has application-specific hardware logic, on-chip memory, and additional on-chip peripherals.

The 'C6701 includes a large bank of on-chip memory and has a powerful and diverse set of peripherals. Program memory consists of a 64K-byte block that is user-configurable as cache or memory-mapped program space. Data memory consists of two 32K-byte blocks of RAM. The peripheral set includes two multichannel buffered serial ports (McBSPs), two general-purpose timers, a host-port interface (HPI), and a glueless external memory interface (EMIF) capable of interfacing to SDRAM or SBSRAM and asynchronous peripherals.

The 'C6701 has a complete set of development tools that includes a new C compiler, an assembly optimizer to simplify programming and scheduling, and a Windows™ debugger interface for visibility into source code execution.

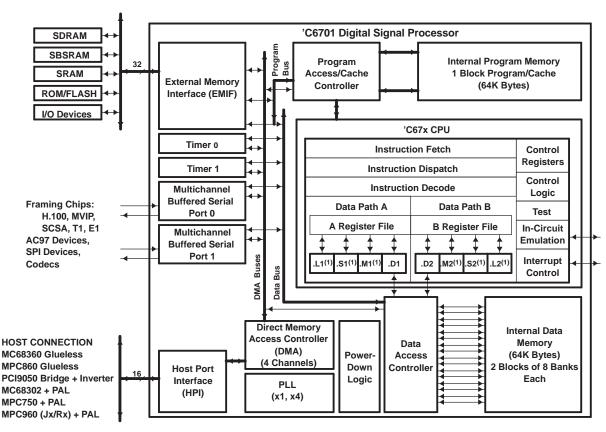
#### **Device Characteristics**

Table 1 provides an overview of the 'C6701 DSP. The table shows significant features of each device, including the capacity of on-chip RAM, the peripherals, the execution time, and the package type with pin count.

Table 1. Characteristics of 'C6701 Processors

CHARACTERISTICS	DESCRIPTION
Device Number	SMJ320C6701
On-Chip Memory	512K-bit Program Memory 512K-bit Data Memory (organized as 2 blocks)
Peripherals	2 Mutichannel Buffered Serial Ports (McBSP) 2 General-Purpose Timers Host-Port Interface (HPI) External Memory Interface (EMIF)
Cycle Time	7 ns at 140 MHz
Package Type	27 mm × 27 mm, 429–Pin BGA (GLP) and 429-Pin LGA (ZMB)
Nominal Voltage	1.9 V Core 3.3 V I/O

#### **Functional and CPU Block Diagram**



(1) These functional units execute floating-point instructions.



#### **CPU Description**

The CPU fetches VelociTl advanced very-long instruction words (VLIW) (256 bits wide) to supply up to eight 32-bit instructions to the eight functional units during every clock cycle. The VelociTl VLIW architecture features controls by which all eight units do not have to be supplied with instructions if they are not ready to execute. The first bit of every 32-bit instruction determines if the next instruction belongs to the same execute packet as the previous instruction, or whether it should be executed in the following clock as a part of the next execute packet. Fetch packets are always 256 bits wide; however, the execute packets can vary in size. The variable-length execute packets are a key memory-saving feature, distinguishing the 'C67x CPU from other VLIW architectures.

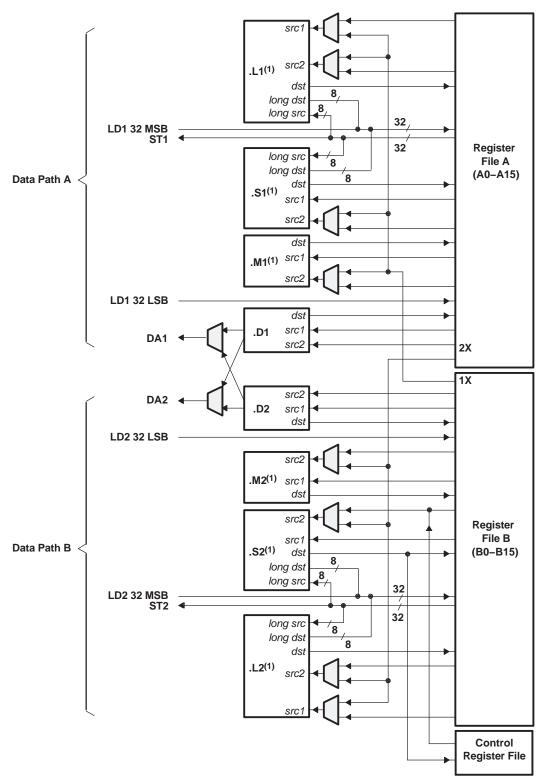
The CPU features two sets of functional units. Each set contains four units and a register file. One set contains functional units .L1, .S1, .M1, and .D1; the other set contains units .D2, .M2, .S2, and .L2. The two register files contain 16 32-bit registers each for the total of 32 general-purpose registers. The two sets of functional units, along with two register files, compose sides A and B of the CPU (see the functional and CPU block diagram and Figure 1). The four functional units on each side of the CPU can freely share the 16 registers belonging to that side. Additionally, each side features a single data bus connected to all registers on the other side, by which the two sets of functional units can access data from the register files on opposite sides. While register access by functional units on the same side of the CPU as the register file can service all the units in a single clock cycle, register access using the register file across the CPU supports one read and one write per cycle.

The 'C67x CPU executes all 'C62x instructions. In addition to 'C62x fixed-point instructions, the six out of eight functional units (.L1, .M1, .D1, .D2, .M2, and .L2) also execute floating-point instructions. The remaining two functional units (.S1 and .S2) also execute the new LDDW instruction which loads 64 bits per CPU side for a total of 128 bits per cycle.

Another key feature of the 'C67x CPU is the load/store architecture, where all instructions operate on registers (as opposed to data in memory). Two sets of data-addressing units (.D1 and .D2) are responsible for all data transfers between the register files and the memory. The data address driven by the .D units allows data addresses generated from one register file to be used to load or store data to or from the other register file. The 'C67x CPU supports a variety of indirect-addressing modes using either linear- or circular-addressing modes with 5- or 15-bit offsets. All instructions are conditional, and most can access any one of the 32 registers. Some registers, however, are singled out to support specific addressing or to hold the condition for conditional instructions (if the condition is not automatically "true"). The two .M functional units are dedicated for multiplies. The two .S and .L functional units perform a general set of arithmetic, logical, and branch functions with results available every clock cycle.

The processing flow begins when a 256-bit-wide instruction fetch packet is fetched from a program memory. The 32-bit instructions destined for the individual functional units are "linked" together by "1" bits in the least significant bit (LSB) position of the instructions. The instructions that are "chained" together for simultaneous execution (up to eight in total) compose an execute packet. A "0" in the LSB of an instruction breaks the chain, effectively placing the instructions that follow it in the next execute packet. If an execute packet crosses the fetch-packet boundary (256 bits wide), the assembler places it in the next fetch packet, while the remainder of the current fetch packet is padded with NOP instructions. The number of execute packets within a fetch packet can vary from one to eight. Execute packets are dispatched to their respective functional units at the rate of one per clock cycle and the next 256-bit fetch packet is not fetched until all the execute packets from the current fetch packet have been dispatched. After decoding, the instructions simultaneously drive all active functional units for a maximum execution rate of eight instructions every clock cycle. While most results are stored in 32-bit registers, they can be subsequently moved to memory as bytes or half-words as well. All load and store instructions are byte, half-word, or word addressable.





(1) These functional units execute floating-point instructions.

Figure 1. SMJ320C67x CPU Data Paths



#### **Signal Groups Description**

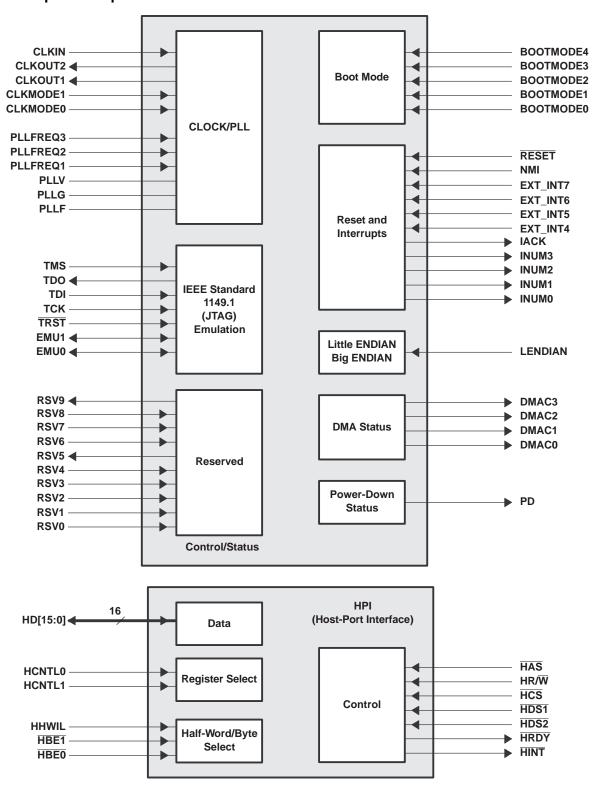


Figure 2. CPU and Peripheral Signals



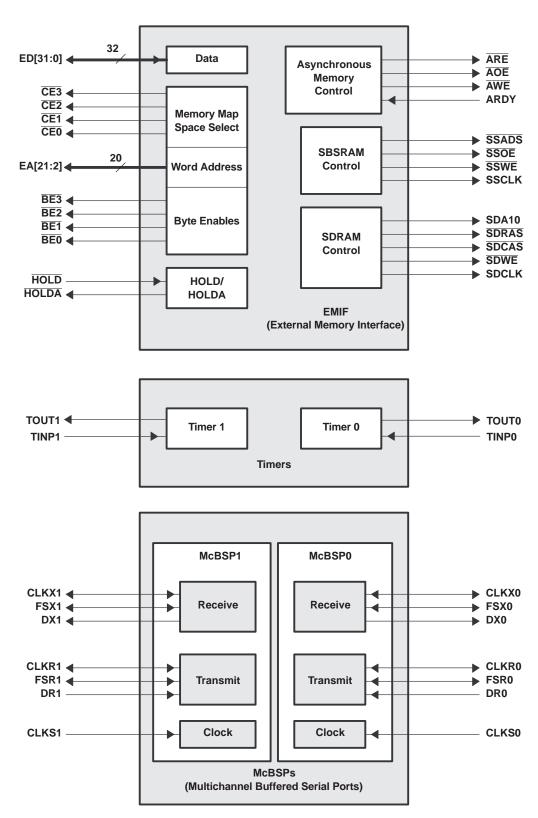


Figure 3. Peripheral Signals



#### **Signal Descriptions**

SIGNA	AL.		
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
			CLOCK/PLL
CLKIN	A14	1	Clock Input
CLKOUT1	Y6	0	Clock output at full device speed
CLKOUT2	V9	0	Clock output at half of device speed
CLKMODE1	B17		Clock mode select
CLKMODE0	C17		• Selects whether the output clock frequency = input clock freq x4 or x1
PLLFREQ3	C13		PLL frequency range (3, 2, and 1)
PLLFREQ2	G11	I	<ul> <li>The target range for CLKOUT1 frequency is determined by the 3-bit value of the</li> </ul>
PLLFREQ1	F11		PLLFREQ pins.
PLLV <sup>(2)</sup>	D12	A <sup>(3)</sup>	PLL analog VCC connection for the low-pass filter
PLLG <sup>(2)</sup>	G10	A <sup>(3)</sup>	PLL analog GND connection for the low-pass filter
PLLF	C12	A <sup>(3)</sup>	PLL low-pass filter connection to external components and a bypass capacitor
			JTAG EMULATION
TMS	K19	I	JTAG test port mode select (features an internal pull-up)
TDO	R12	O/Z	JTAG test port data out
TDI	R13	I	JTAG test port data in (features an internal pull-up)
TCK	M20	I	JTAG test port clock
TRST	N18	I	JTAG test port reset (features an internal pull-down)
EMU1	R20	I/O/Z	Emulation pin 1, pullup with a dedicated 20-kΩ resistor <sup>(4)</sup>
EMU0	T18	I/O/Z	Emulation pin 0, pullup with a dedicated 20-kΩ resistor (4)
			RESET AND INTERRUPTS
RESET	J20	I	Device reset
NMI	K21	ı	Nonmaskable interrupt  • Edge driven (rising edge)
EXT_INT7	R16		
EXT_INT6	P20		External interrupts
EXT_INT5	R15	- 1	Edge driven (rising edge)
EXT_INT4	R18		
IACK	R11	0	Interrupt acknowledge for all active interrupts serviced by the CPU
INUM3	T19		
INUM2	T20		Active interrupt identification number
INUM1	T14	0	<ul> <li>Valid during IACK for all active interrupts (not just external)</li> <li>Encoding order follows the interrupt service fetch packet ordering.</li> </ul>
INUM0	T16	1	Encoding order follows the interrupt service fetch packet ordering.
		1	LITTLE ENDIAN/BIG ENDIAN
LENDIAN	G20	I	If high, selects little-endian byte/half-word addressing order within a word. If low, selects big-endian addressing.
			POWER-DOWN STATUS
PD	D19	0	Power-down mode 2 or 3 (active if high)

<sup>(1)</sup> I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground

<sup>(2)</sup> PLLV and PLLG signals are not part of external voltage supply or ground. See the CLOCK/PLL documentation for information on how to connect those pins.

<sup>(3)</sup> A = Analog signal (PLL filter)

<sup>(4)</sup> For emulation and normal operation, pull up EMU1 and EMU0 with a dedicated 20-kΩ resistor. For boundary scan, pull down EMU1 and EMU0 with a dedicated 20-kΩ resistor.

AL	44	
NO.	TYPE <sup>(1)</sup>	DESCRIPTION
		HOST-PORT INTERFACE (HPI)
H2	O/Z	Host interrupt (from DSP to host)
J6	I	Host control – selects between control, address or data registers
H6	I	Host control – selects between control, address or data registers
E4	I	Host halfword select – first or second halfword (not necessarily high or low order)
G6	I	Host byte select within word or half-word
F6	I	Host byte select within word or half-word
D4	I	Host read or write select
D11		
B11		
A11		
G9		
D10		
A10		
C10		
В9	1/0/7	Host part data (used for transfer of data address and sentral)
F9	1/0/2	Host-port data (used for transfer of data, address and control)
C9		
A9		
B8		
D9		
D8		
В7		
C7		
L6	I	Host address strobe
C5	I	Host chip select
C4	I	Host data strobe 1
K6	I	Host data strobe 2
Н3	0	Host ready (from DSP to host)
		BOOT MODE
B16		
G14		
F15	I	Boot mode
C18		
D17		
	H2 J6 H6 E4 G6 F6 D4 D11 B11 A11 G9 D10 A10 C10 B9 F9 C9 A9 B8 D9 D8 B7 C7 L6 C5 C4 K6 H3 B16 G14 F15 C18	NO.  H2 O/Z  J6 I  H6 I  E4 I  G6 I  F6 I  D4 I  D11  B11  A11  G9  D10  A10  C10  B9  F9  C9  A9  B8  D9  D8  B7  C7  L6 I  C5 I  C4 I  K6 I  H3 O



SIG	NAL		inai besoriptions (sontinues)
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
	EM	IF - CONTROL	SIGNALS COMMON TO ALL TYPES OF MEMORY
CE3	Y5	O/Z	
CE2	V3	O/Z	Memory space enables
CE1	T6	O/Z	<ul> <li>Enabled by bits 24 and 25 of the word address</li> <li>Only one asserted during any external data access</li> </ul>
CE0	U2	O/Z	Only one asserted during any external data access
BE3	R8	O/Z	Byte enable control
BE2	Т3	O/Z	Decoded from the two lowest bits of the internal address
BE1	T2	O/Z	Byte write enables for most types of memory
BE0	R2	O/Z	Can be directly connected to SDRAM read and write mask signal (SDQM)
		1	EMIF - ADDRESS
EA21	L4		
EA20	L3		
EA19	J2		
EA18	J1		
EA17	K1		
EA16	K2		
EA15	L2		
EA14	L1		
EA13	M1		
EA12	M2	O/Z	External address (word address)
EA11	M6	U/Z	LAIGHIAI AUGIESS (WOIG AUGIESS)
EA10	N4		
EA9	N1		
EA8	N2		
EA7	N6		
EA6	P4		
EA5	P3		
EA4	P2		
EA3	P1		
EA2	P6		

	SIGNAL		grial 2000 spriono (commuou)
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
			EMIF - DATA
ED31	U18		
ED30	U20		
ED29	T15		
ED28	V18		
ED27	V17		
ED26	V16		
ED25	T12		
ED24	W17		
ED23	T13		
ED22	Y17		
ED21	T11		
ED20	Y16		
ED19	W15		
ED18	V14		
ED17	Y15		
ED16	R9	1/0/7	External data
ED15	Y14	I/O/Z	External data
ED14	V13		
ED13	AA13		
ED12	T10		
ED11	Y13		
ED10	W12		
ED9	Y12		
ED8	Y11		
ED7	V10		
ED6	AA10		
ED5	Y10		
ED4	W10		
ED3	Y9		
ED2	AA9		
ED1	Y8		
ED0	W9		
		EMIF	- ASYNCHRONOUS MEMORY CONTROL
ĀRĒ	R7	O/Z	Asynchronous memory read enable
ĀOĒ	T7	O/Z	Asynchronous memory output enable
AWE	V5	O/Z	Asynchronous memory write enable
ARDY	R4	l	Asynchronous memory ready input



SIGNAL						
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION			
	EMIF - SYNCHRONOUS BURST SRAM CONTROL					
SSADS	V8	O/Z	SBSRAM address strobe			
SSOE	W7	O/Z	SBSRAM output enable			
SSWE	Y7	O/Z	SBSRAM write enable			
SSCLK	AA8	O/Z	SBSRAM clock			
		EMI	F - SYNCHRONOUS DRAM CONTROL			
SDA10	V7	O/Z	SDRAM address 10 (separate for deactivate command)			
SDRAS	V6	O/Z	SDRAM row address strobe			
SDCAS	W5	O/Z	SDRAM column address strobe			
SDWE	T8	O/Z	SDRAM write enable			
SDCLK	T9	O/Z	SDRAM clock			
			EMIF - BUS ARBITRATION			
HOLD	R6	I	Hold request from the host			
HOLDA	B15	0	Hold request acknowledge to the host			
			TIMERS			
TOUT1	G2	O/Z	Timer 1 or general-purpose output			
TINP1	K3	I	Timer 1 or general-purpose input			
TOUT0	M18	O/Z	Timer 0 or general-purpose output			
TINP0	J18	I	Timer 0 or general-purpose input			
			DMA ACTION COMPLETE			
DMAC3	E18					
DMAC2	F19	0	DMA action complete			
DMAC1	E20		DIVIA action complete			
DMAC0	G16					
		MULTICHA	NNEL BUFFERED SERIAL PORT 1 (McBSP1)			
CLKS1	F4	I	External clock source (as opposed to internal)			
CLKR1	H4	I/O/Z	Receive clock			
CLKX1	J4	I/O/Z	Transmit clock			
DR1	E2	I	Receive data			
DX1	G4	O/Z	Transmit data			
FSR1	F3	I/O/Z	Receive frame sync			
FSX1	F2	I/O/Z	Transmit frame sync			

SIGN	AL	<i>(</i> 1)	
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
		MULTICHA	NNEL BUFFERED SERIAL PORT 0 (McBSP0)
CLKS0	K18	I	Extended clock source (as opposed to internal)
CLKR0	L21	I/O/Z	Receive clock
CLKX0	K20	I/O/Z	Transmit clock
DR0	J21	I	Receive data
DX0	M21	O/Z	Transmit data
FSR0	P16	I/O/Z	Receive frame sync
FSX0	N16	I/O/Z	Transmit frame sync
			RESERVED FOR TEST
RSV0	N21	I	Reserved for testing, pullup with a dedicated 20-kΩ resistor
RSV1	K16	I	Reserved for testing, pullup with a dedicated 20-kΩ resistor
RSV2	B13	I	Reserved for testing, pullup with a dedicated 20-kΩ resistor
RSV3	B14	I	Reserved for testing, pullup with a dedicated 20-kΩ resistor
RSV4	F13	I	Reserved for testing, <b>pulldown</b> with a dedicated 20-kΩ resistor
RSV5	C15	0	Reserved (leave unconnected, do not connect to power or ground)
RSV6	F7	I	Reserved for testing, pullup with a dedicated 20-kΩ resistor
RSV7	D7	I	Reserved for testing, pullup with a dedicated 20-k $\Omega$ resistor
RSV8	B5	I	Reserved for testing, pullup with a dedicated 20-k $\Omega$ resistor
RSV9	F16	0	Reserved (leave unconnected, do not connect to power or ground)
	C14		
	C8		
	E19		
	E3		
	H11		
	H13		
	H9		
	J10		
	J12		
	J14		
$DV_DD$	J19	S	3.3-V supply voltage
	J3		
	J8		
	K11		
	K13		
	K15		
	K7		
	K9		
	L10		
	L12		
	L14		



SI	GNAL		grial Descriptions (continued)
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
		SU	PPLY VOLTAGE PINS (CONTINUED)
	L8		
	M11		
	M13		
	M15		
	M7		
	M9		
	N10		
	N12		
	N14		
$DV_DD$	N19	S	3.3-V supply voltage
	N3		
	N8		
	P11		
	P13		
	P9		
	U19		
	U3		
	W14		
	W8		
	A12		
	A13		
	B10		
	B12 B6		
	D15		
	D16		
	F10		
	F14		
	F8		
CV <sub>DD</sub>	G13	S	1.9-V supply voltage
	G7		
	G8		
	K4		
	M3		
	M4		
	А3		
	A5		
	A7		
	A16		

SIGN	NAL				
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION		
	SUPPLY VOLTAGE PINS (CONTINUED)				
	A18				
	AA4				
	AA6				
	AA15				
	AA17				
	AA19				
	B2				
	B4				
	B19				
	C1				
	C3				
	C20				
	D2				
	D21				
	E1				
	E6				
CV <sub>DD</sub>	E8	S	1.9-V supply voltage		
O 1 DD	E10		The Volume of the Control of the Con		
	E12				
	E14				
	E16				
	F5				
	F17				
	F21				
	G1				
	H5				
	H17				
	K5				
	K17				
	M5				
	M17	- - -			
	P5				
	P17				
	R21				



SI	GNAL		mai bescriptions (continued)
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
		SUF	PPLY VOLTAGE PINS (CONTINUED)
	T1		
	T5		
	T17		
	U6		
	U8		
	U10		
	U12		
	U14		
	U16		
	U21		
	V1		
	V20		
	W2		
	W19		
	W21		
	Y3		
	Y18		
	Y20		
CV <sub>DD</sub>	AA11	S	1.9-V supply voltage
	AA12		
	F20		
	G18		
	H16		
	H18		
	L18		
	L19		
	L20		
	N20		
	P18		
	P19		
	R10		
	R14		
	U4	_	
	V11		
	V12		
	V15		
	W13		

SIGNAL		TVD=(1)	DECODINE
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
			GROUND PINS
	C11		
	C16		
	C6		
	D5		
	G3		
	H10		
	H12		
	H14		
	H7		
	H8		
	J11		
	J13		
	J7		
	J9		
	K8		
	L7		
	L9		
	M8		
	N7		
V <sub>SS</sub>	R3	GND	Ground
	A4		
	A6	-	
	A8		
	A15		
	A17		
	A19 AA3		
	AA5		
	AA5		
	AA14		
	AA16		
	AA18		
	B3		
	B18		
	B20		
	C2		
	C19		
	C21		
	D1		



SI	IGNAL		
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
			GROUND PINS (CONTINUED)
	D20		
	E5		
	E7		
	E9		
	E11		
	E13		
	E15		
	E17		
	E21		
	F1		
	G5		
	G17		
	G21		
	H1		
	J5		
	J17		
	L5	GND	
V <sub>SS</sub>	L17		Ground pins
	N5		
	N17		
	P21		
	R1		
	R5		
	R17		
	T21		
	U1		
	U5		
	U7		
	U9		
	U11		
	U13		
	U15		
	U17		
	V2		
	V21		



SIG	SNAL		DESCRIPTION (COMMISSOR)
NAME	NO.	TYPE <sup>(1)</sup>	DESCRIPTION
			GROUND PINS (CONTINUED)
	W1		
	W3		
	W20		
	Y2		
	Y4		
	Y19		
	F18		
	G19		
	H15		
	J15		
	J16		
	K10		
	K12		
	K14		
	L11		
	L13		
	L15		
$V_{SS}$	M10	GND	Ground pins
	M12		
	M14		
	N11		
	N13		
	N15		
	N9		
	P10		
	P12		
	P14		
	P15		
	P7		
	P8		
	R19		
	T4 W11		
	W16		
	W6		



SIGN	AL	TYPE <sup>(1)</sup>	DECORIDATION
NAME	NO.	ITPE	DESCRIPTION
			REMAINING UNCONNECTED PINS
	D13		
	D14		
	D18		
	D3		
	D6		
	F12		
	G12		
	G15		
NC	H19		Unconnected pins
NO	H20		Onconnected pins
	H21		
	L16		
	M16		
	M19		
	V19		
	V4		
	W18		
	W4		

#### **Development Support**

Texas Instruments (TI) offers an extensive line of development tools for the 'C6x generation of DSPs, including tools to evaluate the performance of the processors, generate code, develop algorithm implementations, and fully integrate and debug software and hardware modules.

The following products support development of 'C6x-based applications:

#### Software-development tools

- Assembly optimizer
- Assembler/Linker
- Simulator
- Optimizing ANSI C compiler
- Application algorithms
- C/Assembly debugger and code profiler

#### • Hardware-development tools

- Extended development system (XDS™) emulator (supports 'C6x multiprocessor system debug)
- EVM (Evaluation Module)

The TMS320 DSP Development Support Reference Guide (SPRU011) contains information about development-support products for all TMS320 family member devices, including documentation. See this document for further information on TMS320 documentation or any TMS320 support products from Texas Instruments. An additional document, the TMS320 Third-Party Support Reference Guide (SPRU052), contains information about TMS320-related products from other companies in the industry. To receive TMS320 literature, contact the Literature Response Center at 800/477-8924.

See Table 2 for a complete listing of development-support tools for the 'C6x. For information on pricing and availability, contact the nearest TI field sales office or authorized distributor.

Table 2. SMJ320C6x Development-Support Tools

DEVELOPMENT TOOL	PLATFORM	PART NUMBER
,	Software	
Ada 95 Compiler <sup>(1)</sup>	Sun Solaris 2.3 <sup>™ (2)</sup>	AD0345AS8500RF – Single user AD0345BS8500RF – Multi user
C Compiler/Assembler/Linker/Assembly Optimizer	Win32™	TMDX3246855-07
C Compiler/Assembler/Linker/Assembly Optimizer	SPARC™ Solaris™	TMDX3246555-07
Simulator	Win32	TMDS3246851-07
Simulator	SPARC Solaris	TMDS3246551-07
XDS510™ Debugger/Emulation Software	Win32, Windows NT™	TMDX324016X-07
	Hardware	
XDS510 Emulator <sup>(3)</sup>	PC	TMDS00510
XDS510WS™ Emulator <sup>(4)</sup>	SCSI	TMDS00510WS
	Software/Hardware	
EVM Evaluation Kit	PC/Win95/Windows NT	TMDX3260A6201
EVM Evaluation Kit (including TMDX3246855-07)	PC/Win95/Windows NT	TMDX326006201

<sup>(1)</sup> Contact IRVINE Compiler Corporation (949) 250-1366 to order

(4) Includes XDS510WS box, SCSI cable, power supply, and JTAG emulation cable.

<sup>(2)</sup> NT support estimated availability 1Q00

<sup>(3)</sup> Includes XDS510 board and JTAG emulation cable. TMDX324016X-07 C-source Debugger/Emulation software is not included.



#### **Device and Development-Support Tool Nomenclature**

To designate the stages in the product-development cycle, TI assigns prefixes to the part numbers of all SMJ320 devices and support tools. Each SMJ320 member has one of three prefixes: SMX, SM, or SMJ. Texas Instruments recommends two of three possible prefix designators for support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (SMX/TMDX) through fully qualified production devices/tools (SMJ/TMDS).

Device development evolutionary flow:

**SMX** Experimental device that is not necessarily representative of the final device's electrical

specifications

**SM** Final silicon die that conforms to the device's electrical specifications but has not completed

quality and reliability verification

**SMJ** Fully qualified production device processed to MIL-PRF-38535

Support tool development evolutionary flow:

**TMDX** Development-support product that has not yet completed Texas Instruments internal

qualification testing.

**TMDS** Fully qualified development-support product

SMX devices and TMDX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

SMJ devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (SMX or SM) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the package type (for example, GLP), the temperature range, and the device speed range in megahertz (for example, 14 is 140 MHz). Figure 4 provides a legend for reading the complete device name for any SMJ320 family member.



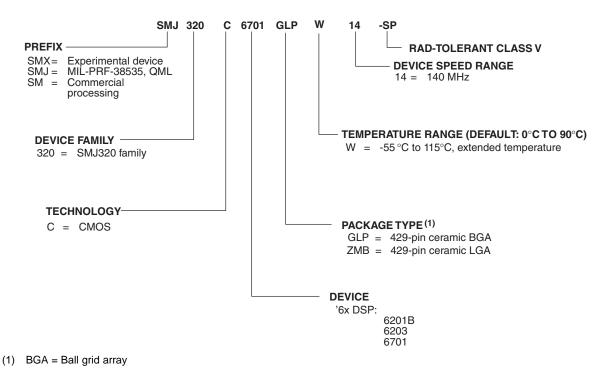


Figure 4. SMJ320 Device Nomenclature (Including SMJ320C6701-SP)

#### **Documentation Support**

Extensive documentation supports all SMJ320 family generations of devices from product announcement through applications development. The types of documentation available include: data sheets, such as this document, with design specifications; complete user's reference guides for all devices; technical briefs; development-support tools; and hardware and software applications. The following is a brief, descriptive list of support documentation specific to the 'C6x devices:

The *TMS320C6000 CPU* and *Instruction Set Reference Guide* (literature number SPRU189) describes the 'C6000 CPU architecture, instruction set, pipeline, and associated interrupts.

The *TMS320C6000 Peripherals Reference Guide* (literature number SPRU190) describes the functionality of the peripherals available on 'C6x devices, such as the external memory interface (EMIF), host-port interface (HPI), multichannel buffered serial ports (McBSPs), direct-memory-access (DMA), enhanced direct-memory-access (EDMA) controller, expansion bus (XB), clocking and phase-locked loop (PLL); and power-down modes. This guide also includes information on internal data and program memories.

The *TMS320C6000 Programmer's Guide* (literature number SPRU198) describes ways to optimize C and assembly code for 'C6x devices and includes application program examples.

The TMS320C6x C Source Debugger User's Guide (literature number SPRU188) describes how to invoke the 'C6x simulator and emulator versions of the C source debugger interface and discusses various aspects of the debugger, including: command entry, code execution, data management, breakpoints, profiling, and analysis.

The TMS320C6x Peripheral Support Library Programmer's Reference (literature number SPRU273) describes the contents of the 'C6x peripheral support library of functions and macros. It lists functions and macros both by header file and alphabetically, provides a complete description of each, and gives code examples to show how they are used.

TMS320C6000 Assembly Language Tools User's Guide (literature number SPRU186) describes the assembly language tools (assembler, linker, and other tools used to develop assembly language code), assembler directives, macros, common object file format, and symbolic debugging directives for the 'C6000 generation of devices.



The *TMS320C6x Evaluation Module Reference Guide* (literature number SPRU269) provides instructions for installing and operating the 'C6x evaluation module. It also includes support software documentation, application programming interfaces, and technical reference material.

TMS320C6000 DSP/BIOS User's Guide (literature number SPRU303) describes how to use DSP/BIOS tools and APIs to analyze embedded real-time DSP applications.

Code Composer User's Guide (literature number SPRU296) explains how to use the Code Composer development environment to build and debug embedded real-time DSP applications.

Code Composer Studio Tutorial (literature number SPRU301) introduces the Code Composer Studio integrated development environment and software tools.

The *TMS320C6000 Technical Brief* (literature number SPRU197) gives an introduction to the 'C62x/C67x devices, associated development tools, and third-party support.

A series of DSP textbooks is published by Prentice-Hall and John Wiley & Sons to support DSP research and education. The TMS320 newsletter, *Details on Signal Processing*, is published quarterly and distributed to update SMJ320 customers on product information. The TMS320 DSP bulletin board service (BBS) provides access to information pertaining to the SMJ320 family, including documentation, source code, and object code for many DSP algorithms and utilities. The BBS can be reached at 281/274-2323.

Information regarding TI DSP products is also available on the Worldwide Web at http://www.ti.com uniform resource locator (URL).

#### **Clock PLL**

All of the internal 'C67x clocks are generated from a single source through the CLKIN pin. This source clock either drives the PLL, which multiplies the source clock in frequency to generate the internal CPU clock, or bypasses the PLL to become the internal CPU clock.

To use the PLL to generate the CPU clock, the external PLL filter circuit must be properly designed. Table 3, Table 4, and Figure 5 show the external PLL circuitry for either x1 (PLL bypass) or x4 PLL multiply modes. Table 3 and Figure 6 show the external PLL circuitry for a system with ONLY x1 (PLL bypass) mode.

To minimize the clock jitter, a single clean power supply should power both the 'C67x device and the external clock oscillator circuit. Noise coupling into PLLF will directly impact PLL clock jitter. The minimum CLKIN rise and fall times should also be observed. For the input clock timing requirements, see the *input and output clocks* electricals section. Guidelines for EMI filter selection are as follows: maximum attenuation frequency = 20–30 MHz, maximum dB attenuation = 45–50 dB, and minimum dB attenuation above 30 MHz = 20 dB.

Table 3. CLKOUT1 Frequency Ranges<sup>(1)</sup>

PLLFREQ3	PLLFREQ2	PLLFREQ1	CLKOUT1 FREQUENCY RANGE
(C13)	(G11)	(F11)	(MHz)
0	0	0	

(1) Due to overlap of frequency ranges when choosing the PLLFREQ, more than one frequency range can contain the CLKOUT1 frequency. Choose the lowest frequency range that includes the desired frequency. For example, for CLKOUT1 = 133 MHz, choose PLLFREQ value of 000b. PLLFREQ values other than 000b, 001b, and 010b are reserved.

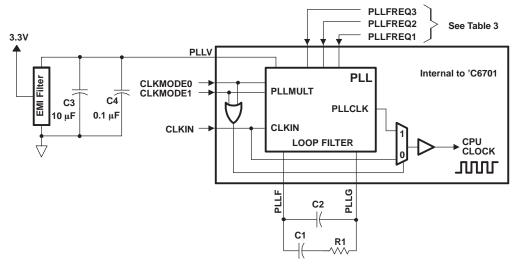
Table 4. 'C6701 PLL Component Selection Table

CLKMODE	CLKIN RANGE (MHz)	CPU CLOCK FREQUENCY (CLKOUT1) RANGE (MHz)	CLKOUT2 RANGE (MHz)	R1 (W)	C1 (nF)	C2 (pF)	TYPICAL LOCK TIME (μs) <sup>(1)</sup>
x4	12.5 – 41.7	50-140	25 – 83.5	60.4	27	560	75

(1) Under some operating conditions, the maximum PLL lock time may vary as much as 150% from the specified typical value. For example, if the typical lock time is specified as 100 μs, the maximum value may be as long as 250 μs.

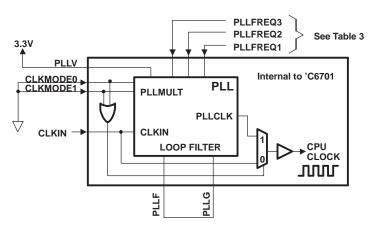
24

AVAILABLE MULTIPLY FACTORS								
CLKMODE1	CLKMODE0	CLKMODE0 PLL MULTIPLY FACTORS CPU CLOCK FREQUENCY F(CPUCLOCK)						
0	0	x1(BYPASS)	1 x f(CLKIN)					
0	1	Reserved	Reserved					
1	0	Reserved	Reserved					
1	1	x4	4 x f(CLKIN)					



- (1) Keep the lead length and the number of vias between the PLLF pin, the PLLG pin, and R1, C1, and C2 to a minimum. In addition, place all PLL external components (R1, C1, C2, C3, C4, and the EMI filter) as close to the 'C6000 device as possible. For the best performance, TI recommends that all the PLL external components be on a single side of the board without jumpers, switches, or components other than the ones shown.
- (2) For reduced PLL jitter, maximize the spacing between switching signals and the PLL external components (R1, C1, C2, C3, C4, and the EMI filter).
- (3) The 3.3-V supply for the EMI filter must be from the same 3.3-V power plane supplying the I/O voltage, DV<sub>DD</sub>.

Figure 5. External PLL Circuitry for Either PLL ×4 Mode or ×1 (Bypass) Mode



- (1) For a system with ONLY PLL x1 (bypass) mode, short the PLLF terminal to the PLLG terminal.
- (2) The 3.3-V supply for the EMI filter must be from the same 3.3-V power plane supplying the I/O voltage, DV<sub>DD</sub>.

Figure 6. External PLL Circuitry for ×1 (Bypass) Mode Only



#### **Power-Supply Sequencing**

TI DSPs do not require specific power sequencing between the core supply and the I/O supply. However, systems should be designed to ensure that neither supply is powered up for extended periods of time if the other supply is below the proper operating voltage.

#### **System-Level Design Considerations**

System-level design considerations, such as bus contention, may require supply sequencing to be implemented. In this case, the core supply should be powered up at the same time as, or prior to (and powered down after), the I/O buffers. This is to ensure that the I/O buffers receive valid inputs from the core before the output buffers are powered up, thus, preventing bus contention with other chips on the board.

#### **Power-Supply Design Considerations**

For systems using the C6000™ DSP platform of devices, the core supply may be required to provide in excess of 2 A per DSP until the I/O supply is powered up. This extra current condition is a result of uninitialized logic within the DSP(s) and is corrected once the CPU sees an internal clock pulse. With the PLL enabled, as the I/O supply is powered on, a clock pulse is produced stopping the extra current draw from the supply. With the PLL disabled, an external clock pulse may be required to stop this extra current draw. A normal current state returns once the I/O power supply is turned on and the CPU sees a clock pulse. Decreasing the amount of time between the core supply power up and the I/O supply power up can minimize the effects of this current draw.

A dual-power supply with simultaneous sequencing, such as available with TPS563xx controllers or PT69xx plug-in power modules, can be used to eliminate the delay between core and I/O power up [see the Using the TPS56300 to Power DSPs application report (literature number SLVA088)]. A Schottky diode can also be used to tie the core rail to the I/O rail, effectively pulling up the I/O power supply to a level that can help initialize the logic within the DSP.

Core and I/O supply voltage regulators should be located close to the DSP (or DSP array) to minimize inductance and resistance in the power delivery path. Additionally, when designing for high-performance applications utilizing the C6000™ platform of DSPs, the PC board should include separate power planes for core, I/O, and ground, all bypassed with high-quality low-ESL/ESR capacitors.

Submit Documentation Feedback

## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$CV_{DD}$	Supply voltage range (2)		-0.3	2.3	V
$DV_DD$	V <sub>DD</sub> Supply voltage range <sup>(2)</sup>			4	V
	Input voltage range			4	V
	Output voltage range		-0.3	4	V
т	Operating cope temperature range	S-suffix device		90	°C
T <sub>C</sub>	Operating case temperature range	W-suffix device	-55	115	C
T <sub>stg</sub>	Storage temperature range		-55	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### **Recommended Operating Conditions**

			MIN	NOM	MAX	UNIT	
$CV_{DD}$	Supply voltage	1.81	1.9	1.99	V		
$DV_DD$	Supply voltage		3.14	3.3	3.46	V	
$V_{SS}$	Supply ground			0	0	V	
$V_{IH}$	High-level input voltage					V	
$V_{IL}$	Low-level input voltage				0.8	V	
$I_{OH}$	High-level output current				-12	mA	
I <sub>OL</sub>	Low-level output current				12	mA	
_	Casa tamparatura	S-suffix device	-40		90	°C	
T <sub>C</sub>	Case temperature	W-suffix device	-55		115		

<sup>(2)</sup> All voltage values are with respect to VSS.



#### **Electrical Characteristics**

over recommended ranges of supply voltage and operating case temperature (unless otherwise noted) (unchanged after 100 kRad)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>OH</sub>	High-level output voltage	$DV_{DD} = MIN, I_{OH} = MAX$	2.4			V
V <sub>OL</sub>	Low-level output voltage	$DV_{DD} = MIN, I_{OL} = MAX$			0.6	V
II	Input current <sup>(1)</sup>	$V_I = V_{SS}$ to $DV_{DD}$			±10	μΑ
$I_{OZ}$	Off-state output current	$V_O = DV_{DD}$ or 0 V			±10	μΑ
I <sub>DD2V</sub>	Supply current, CPU + CPU memory access (2)	CV <sub>DD</sub> = NOM, CPU clock = 150 MHz		470		mA
$I_{DD2V}$	Supply current, peripherals <sup>(3)</sup>	CV <sub>DD</sub> = NOM, CPU clock = 150 MHz		250		mA
I <sub>DD3V</sub>	Supply current, I/O pins (4)	DV <sub>DD</sub> = NOM, CPU clock = 150 MHz		85		mA
Ci	Input capacitance				15 <sup>(5)</sup>	pF
Co	Output capacitance				15 <sup>(5)</sup>	pF

<sup>(1)</sup> TMS and TDI are not included due to internal pullups.

TRST is not included due to internal pulldown.

(2) Measured with average CPU activity:
50% of time: 8 instructions per cycle, 32-bit DMEM access per cycle
50% of time: 2 instructions per cycle, 16-bit DMEM access per cycle

50% of time: 2 instructions per cycle, 16-bit DMEM access per cycle
(3) Measured with average peripheral activity:
50% of time: Timers at max rate, McBSPs at E1 rate, and DMA burst transfer between DMEM and SDRAM

50% of time: Timers at max rate, McBSPs at E1 rate, and DMA servicing McBSPs (4) Measured with average I/O activity (30-pF load, SDCLK on):

25% of time: Reads from external SDRAM

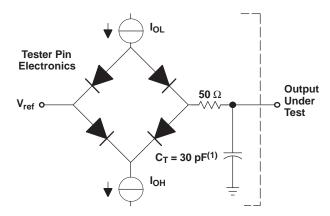
25% of time: Writes to external SDRAM

50% of time: No activity

(5) This parameter is not tested.



#### PARAMETER MEASUREMENT INFORMATION



(1) Typical distributed load circuit capacitance.

#### **Signal-Transition Levels**

All input and output timing parameters are referenced to 1.5 V for both "0" and "1" logic levels.



Figure 7. Input and Output Voltage Reference Levels for AC Timing Measurements



#### INPUT AND OUTPUT CLOCKS

## Timing Requirements for CLKIN<sup>(1)</sup>

(see Figure 8)

NO.			CLKMODE =	CLKMODE = x4		CLKMODE = x1	
NO.			MIN	MAX	MIN	MAX	UNIT
1	t <sub>c(CLKIN)</sub>	Cycle time, CLKIN	28.4		7.1		ns
2	t <sub>w(CLKINH)</sub>	Pulse duration, CLKIN high	0.4C <sup>(2)(3)</sup>		0.45C <sup>(2)(3)</sup>		ns
3	t <sub>w(CLKINL)</sub>	Pulse duration, CLKIN low	0.4C <sup>(2)(3)</sup>		0.45C <sup>(2)(3)</sup>		ns
4	t <sub>t(CLKIN)</sub>	Transition time, CLKIN		5 <sup>(2)</sup>		0.6(2)	ns

- The reference points for the rise and fall transitions ar measured at 20% and 80%, respectively, of  $V_{IH}$ .
- This parameter is not tested.
- C = CLKIN cycle time in ns. For example, when CLKIN frequency is 10 MHz, use C = 100 ns.

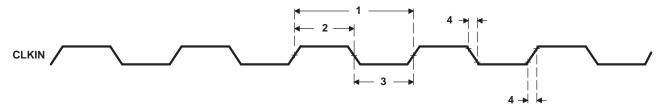


Figure 8. CLKIN Timing

## Switching Characteristics for CLKOUT1 (1)(2)

(see Figure 9)

NO	PARAMETER		CLKMO	DE = x4	CLKMOI	UNIT	
NO.			MIN	MAX	MIN	MAX	UNII
1	t <sub>c(CKO1)</sub>	Cycle time, CLKOUT1	$P - 0.7^{(3)}$	P + 0.7 <sup>(3)</sup>	$P - 0.7^{(3)}$	P + 0.7 <sup>(3)</sup>	ns
2	t <sub>w(CKO1H)</sub>	Pulse duration, CLKOUT1 high	$(P/2) - 0.5^{(3)}$	$(P/2) + 0.5^{(3)}$	PH – 0.5 <sup>(3)</sup>	PH + 0.5 <sup>(3)</sup>	ns
3	t <sub>w(CKO1L)</sub>	Pulse duration, CLKOUT1 low	$(P/2) - 0.5^{(3)}$	$(P/2) + 0.5^{(3)}$	PL - 0.5 <sup>(3)</sup>	PL + 0.5 <sup>(3)</sup>	ns
4	t <sub>t</sub> (CKO1)	Transition time, CLKOUT1		0.6(3)		0.6(3)	ns

- P = 1/CPU clock frequency in nanoseconds (ns).
  PH is the high period of CLKIN in ns and PL is the low period of CLKIN in ns.
- This parameter is not tested.

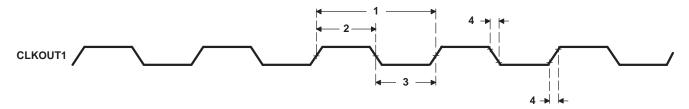


Figure 9. CLKOUT1 Timing

#### Switching Characteristics for CLKOUT2<sup>(1)</sup>

(see Figure 10)

NO.		PARAMETER	MIN	MAX	UNIT
1	t <sub>c(CKO2)</sub>	Cycle time, CLKOUT2	2P - 0.7 <sup>(2)</sup>	2P + 0.7 <sup>(2)</sup>	ns
2	t <sub>w(CKO2H)</sub>	Pulse duration, CLKOUT2 high	P - 0.7 <sup>(2)</sup>	P + 0.7 <sup>(2)</sup>	ns
3	t <sub>w(CKO2L)</sub>	Pulse duration, CLKOUT2 low	P - 0.7 <sup>(2)</sup>	P + 0.7 <sup>(2)</sup>	ns
4	t <sub>t(CKO2)</sub>	Transition time, CLKOUT2		0.6 <sup>(2)</sup>	ns

- (1) P = 1/CPU clock frequency in ns.
- (2) This parameter is not tested.

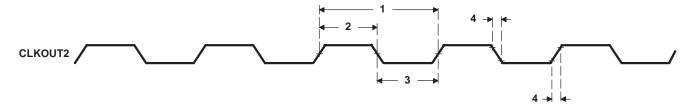


Figure 10. CLKOUT2 Timing

#### **SDCLK, SSCLK Timing Parameter**

SDCLK timing parameters are the same as CLKOUT2 parameters.

SSCLK timing parameters are the same as CLKOUT1 or CLKOUT2 parameters, depending on SSCLK configuration.

# Switching Characteristics for the Relation of SSCLK, SDCLK, and CLKOUT2 to CLKOUT1 (see Figure 11)

NO.		PARAMETER	MIN	MAX	UNIT
1	t <sub>d(CKO1-SSCLK)</sub>	Delay time, CLKOUT1 edge to SSCLK edge	-0.8	3.4	ns
2	t <sub>d(CKO1-SSCLK1/2)</sub>	Delay time, CLKOUT1 edge to SSCLK edge (1/2 clock rate)	-1	3	ns
3	t <sub>d(CKO1-CKO2)</sub>	Delay time, CLKOUT1 edge to CLKOUT2 edge	-1.5	2.5	ns
4	t <sub>d(CKO1-SDCLK)</sub>	Delay time, CLKOUT1 edge to SDCLK edge	-1.5	1.9	ns

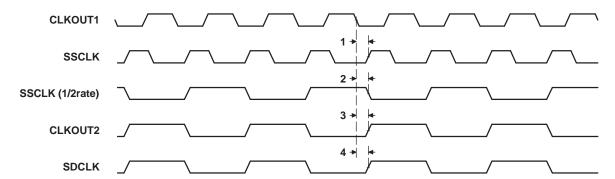


Figure 11. Relation of CLKOUT2, SDCLK, and SSCLK to CLKOUT1



#### **ASYNCHRONOUS MEMORY TIMING**

## Timing Requirements for Asynchronous Memory Cycles<sup>(1)</sup>

(see Figure 12 and Figure 13)

NO.			MIN	MAX	UNIT
6	t <sub>su(EDV-CKO1H)</sub>	Setup time, read EDx valid before CLKOUT1 high	4.8		ns
7	t <sub>h(CKO1H-EDV)</sub>	Hold time, read EDx valid after CLKOUT1 high	1.5		ns
10	t <sub>su(ARDY-CKO1H)</sub>	Setup time, ARDY valid before CLKOUT1 high	3.5		ns
11	t <sub>h(CKO1H-ARDY)</sub>	Hold time, ARDY valid after CLKOUT1 high	1.5		ns

<sup>(1)</sup> To ensure data setup time, simply program the strobe width wide enough. ARDY is internally synchronized. If ARDY does meet setup or hold time, it may be recognized in the current cycle or the next cycle. Thus, ARDY can be an asynchronous input.

## Switching Characteristics for Asynchronous Memory Cycles<sup>(1)</sup>

(see Figure 12 and Figure 13)

NO.		PARAMETER	MIN	MAX	UNIT
1	t <sub>d(CKO1H</sub> -CEV)	Delay time, CLKOUT1 high to CEx valid	-1	4.5	ns
2	t <sub>d(CKO1H-BEV)</sub>	Delay time, CLKOUT1 high to BEx valid		4.5	ns
3	t <sub>d(CKO1H</sub> BEIV)	Delay time, CLKOUT1 high to BEx invalid	-1		ns
4	t <sub>d(CKO1H-EAV)</sub>	Delay time, CLKOUT1 high to EAx valid		4.5	ns
5	t <sub>d(CKO1H-EAIV)</sub>	Delay time, CLKOUT1 high to EAx invalid	-1		ns
8	t <sub>d(CKO1H-AOEV)</sub>	Delay time, CLKOUT1 high to AOE valid	-1	4.5	ns
9	t <sub>d(CKO1H-AREV)</sub>	Delay time, CLKOUT1 high to ARE valid	-1	4.5	ns
12	t <sub>d(CKO1H-EDV)</sub>	Delay time, CLKOUT1 high to EDx valid		4.5	ns
13	t <sub>d(CKO1H</sub> EDIV)	Delay time, CLKOUT1 high to EDx invalid	-1		ns
14	t <sub>d(CKO1H</sub> -AWEV)	Delay time, CLKOUT1 high to AWE valid	-1	4.5	ns

(1) The minimum delay is also the minimum output hold after CLKOUT1 high.

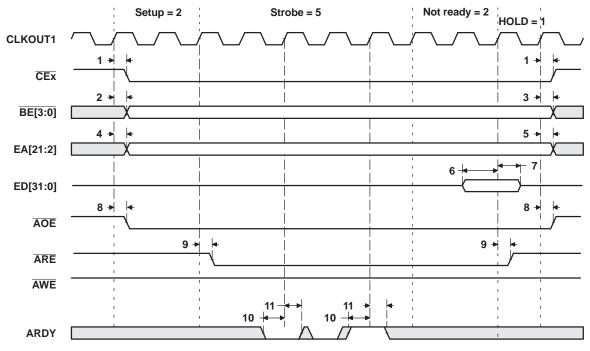


Figure 12. Asynchronous Memory Read Timing

32

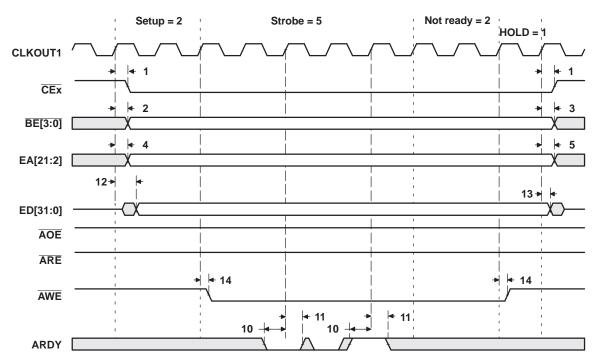


Figure 13. Aysnchronous Memory Write Timing



#### SYNCHRONOUS-BURST MEMORY TIMING

#### Timing Requirements for Synchronous-Burst SRAM Cycles (Full-Rate SSCLK)

(see Figure 14)

NO.			MIN	MAX	UNIT
7	t <sub>su(EDV</sub> -SSCLKH)	Setup time, read EDx valid before SSCLK high	2.6		ns
8	t <sub>h(SSCLKH-EDV)</sub>	Hold time, read EDx valid after SSCLK high	1.5		ns

## Switching Characteristics for Synchronous-burst SRAM Cycles<sup>(1)</sup> (Full-Rate SSCLK)

(see Figure 14 and Figure 15)

NO.		PARAMETER	MIN MAX	UNIT
1	t <sub>osu(CEV</sub> -SSCLKH)	Output setup time, CEx valid before SSCLK high	0.5P - 1.5	ns
2	toh(SSCLKH-CEV)	Output hold time, CEx valid after SSCLK high	0.5P - 2.5	ns
3	t <sub>osu(BEV-SSCLKH)</sub>	Output setup time, BEx valid before SSCLK high	0.5P - 1.6	ns
4	toh(SSCLKH-BEIV)	Output hold time, BEx invalid after SSCLK high	0.5P - 2.5	ns
5	t <sub>osu(EAV-SSCLKH)</sub>	Output setup time, EAx valid before SSCLK high	0.5P - 1.7	ns
6	toh(SSCLKH-EAIV)	Output hold time, EAx invalid after SSCLK high	0.5P - 2.5	ns
9	t <sub>osu(ADSV-SSCLKH)</sub>	Output setup time, SSADS valid before SSCLK high	0.5P - 1.5	ns
10	toh(SSCLKH-ADSV)	Output hold time, SSADS valid after SSCLK high	0.5P - 2.5	ns
11	t <sub>osu(OEV</sub> -SSCLKH)	Output setup time, SSOE valid before SSCLK high	0.5P - 1.5	ns
12	toh(SSCLKH-OEV)	Output hold time, SSOE valid after SSCLK high	0.5P - 2.5	ns
13	t <sub>osu(EDV</sub> -SSCLKH)	Output setup time, EDx valid before SSCLK high	0.5P - 1.5	ns
14	toh(SSCLKH-EDIV)	Output hold time, EDx invalid after SSCLK high	0.5P - 2.5	ns
15	t <sub>osu(WEV-SSCLKH)</sub>	Output setup time, SSWE valid before SSCLK high	0.5P - 1.5	ns
16	toh(SSCLKH-WEV)	Output hold time, SSWE valid after SSCLK high	0.5P - 2.5	ns

<sup>(1)</sup> The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. When the PLL is used (CLKMODE x4), P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. For CLKMODE x1, 0.5P is defined as PH (pulse duration of CLKIN high) for all output setup times; 0.5P is defined as PL (pulse duration of CLKIN low) for all output hold times.

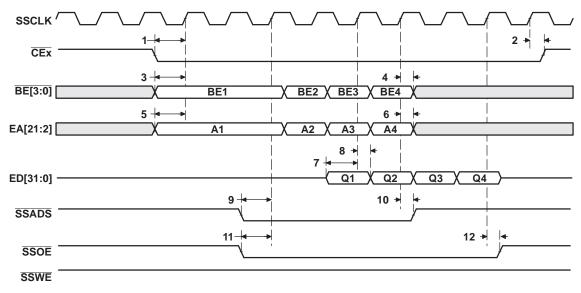


Figure 14. SBSRAM Read Timing (Full-Rate SSCLK)

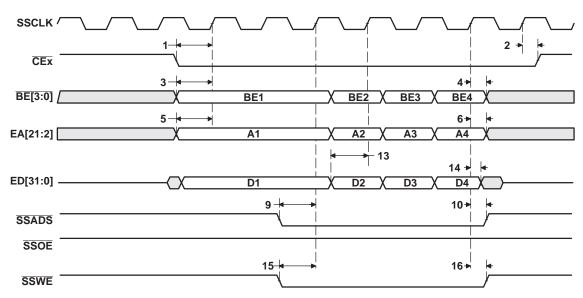


Figure 15. SBSRAM Write Timing (Full-Rate SSCLK)

#### Timing Requirements for Synchronous-Burst SRAM Cycles (Half-Rate SSCLK)

(seeFigure 16)

NO.			MIN	MAX	UNIT
7	t <sub>su(EDV</sub> -SSCLKH)	Setup time, read EDx valid before SSCLK high	3.8		ns
8	t <sub>h</sub> (SSCLKH-EDV)	Hold time, read EDx valid after SSCLK high	1.5		ns

## Switching Characteristics for Synchronous-Burst SRAM Cycles<sup>(1)</sup> (Half-Rate SSCLK)

(see Figure 16 and Figure 17)

NO.		PARAMETER	MIN MAX	UNIT
1	t <sub>osu(CEV-SSCLKH)</sub>	Output setup time, CEx valid before SSCLK high	1.5P - 5.5	ns
2	toh(SSCLKH-CEV)	Output hold time, CEx valid after SSCLK high	0.5P - 2.3	ns
3	t <sub>osu(BEV</sub> -SSCLKH)	Output setup time, BEx valid before SSCLK high	1.5P - 5.5	ns
4	toh(SSCLKH-BEIV)	Output hold time, BEx invalid after SSCLK high	0.5P - 2.3	ns
5	t <sub>osu(EAV-SSCLKH)</sub>	Output setup time, EAx valid before SSCLK high	1.5P - 5.5	ns
6	toh(SSCLKH-EAIV)	Output hold time, EAx invalid after SSCLK high	0.5P - 2.3	ns
9	t <sub>osu(ADSV</sub> -SSCLKH)	Output setup time, SSADS valid before SSCLK high	1.5P - 5.5	ns
10	toh(SSCLKH-ADSV)	Output hold time, SSADS valid after SSCLK high	0.5P - 2.3	ns
11	t <sub>osu(OEV</sub> -SSCLKH)	Output setup time, SSOE valid before SSCLK high	1.5P - 5.5	ns
12	toh(SSCLKH-OEV)	Output hold time, SSOE valid after SSCLK high	0.5P - 2.3	ns
13	t <sub>osu(EDV</sub> -SSCLKH)	Output setup time, EDx valid before SSCLK high	1.5P - 5.5	ns
14	toh(SSCLKH-EDIV)	Output hold time, EDx invalid after SSCLK high	0.5P - 2.3	ns
15	t <sub>osu(WEV-SSCLKH)</sub>	Output setup time, SSWE valid before SSCLK high	1.5P - 5.5	ns
16	t <sub>oh(SSCLKH-WEV)</sub>	Output hold time, SSWE valid after SSCLK high	0.5P - 2.3	ns

<sup>(1)</sup> The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. When the PLL is used (CLKMODE x4), P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. For CLKMODE x1:

<sup>1.5</sup>P = P + PH, where P = 1/CPU clock frequency, and PH = pulse duration of CLKIN high.

<sup>0.5</sup>P = PL, where PL = pulse duration of CLKIN low.



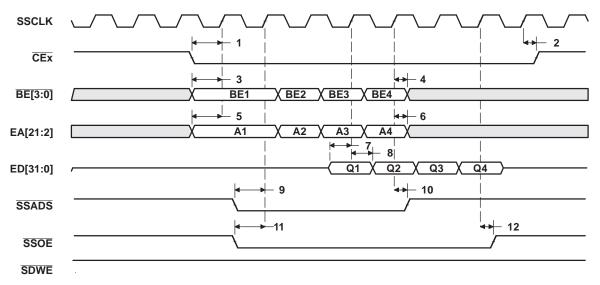


Figure 16. SBSRAM Read Timing (Half-Rate SSCLK)

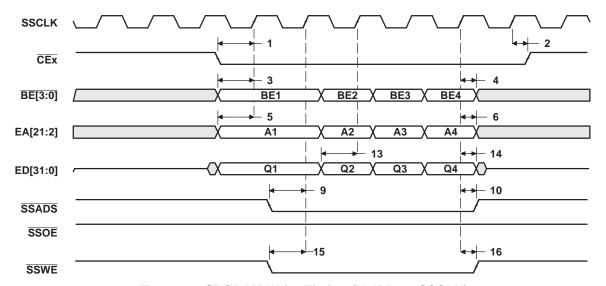


Figure 17. SBSRAM Write Timing (Half-Rate SSCLK)

## SYNCHRONOUS DRAM TIMING

## **Timing Requirements for Synchronous DRAM Cycles**

(see Figure 18)

NO.			MIN	MAX	UNIT
7	t <sub>su(EDV-SDCLKH)</sub>	Setup time, read EDx valid before SDCLK high	2		ns
8	t <sub>h(SDCLKH-EDV)</sub>	Hold time, read EDx valid after SDCLK high	3		ns

# Switching Characteristics for Synchronous DRAM Cycles<sup>(1)</sup>

(see Figure 18 – Figure 23)

NO.		PARAMETER	MIN MAX	UNIT
1	t <sub>osu(CEV-SDCLKH)</sub>	Output setup time, CEx valid before SDCLK high	1.5P – 5	ns
2	t <sub>oh(SDCLKH-CEV)</sub>	Output hold time, CEx valid after SDCLK high	0.5P - 1.9	ns
3	t <sub>osu(BEV-SDCLKH)</sub>	Output setup time, BEx valid before SDCLK high	1.5P – 5	ns
4	t <sub>oh(SDCLKH-BEIV)</sub>	Output hold time, BEx invalid after SDCLK high	0.5P - 1.9	ns
5	t <sub>osu(EAV-SDCLKH)</sub>	Output setup time, EAx valid before SDCLK high	1.5P – 5	ns
6	toh(SDCLKH-EAIV)	Output hold time, EAx invalid after SDCLK high	0.5P - 1.9	ns
9	t <sub>osu(SDCAS-SDCLKH)</sub>	Output setup time, SDCAS valid before SDCLK high	1.5P – 5	ns
10	t <sub>oh(SDCLKH-SDCAS)</sub>	Output hold time, SDCAS valid after SDCLK high	0.5P - 1.9	ns
11	t <sub>osu(EDV</sub> -SDCLKH)	Output setup time, EDx valid before SDCLK high	1.5P – 5	ns
12	t <sub>oh(SDCLKH-EDIV)</sub>	Output hold time, EDx invalid after SDCLK high	0.5P - 1.9	ns
13	t <sub>osu(SDWE</sub> -SDCLKH)	Output setup time, SDWE valid before SDCLK high	1.5P – 5	ns
14	t <sub>oh(SDCLKH-SDWE)</sub>	Output hold time, SDWE valid after SDCLK high	0.5P - 1.9	ns
15	t <sub>osu(SDA10V-SDCLKH)</sub>	Output setup time, SDA10 valid before SDCLK high	1.5P – 5	ns
16	toh(SDCLKH-SDA10IV)	Output hold time, SDA10 invalid after SDCLK high	0.5P - 1.9	ns
17	t <sub>osu(SDRAS-SDCLKH)</sub>	Output setup time, SDRAS valid before SDCLK high	1.5P – 5	ns
18	toh(SDCLKH-SDRAS)	Output hold time, SDRAS valid after SDCLK high	0.5P - 1.9	ns

<sup>(1)</sup> The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. When the PLL is used (CLKMODE x4), P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. For CLKMODE x1:

<sup>1.5</sup>P = P + PH, where P = 1/CPU clock frequency, and PH = pulse duration of CLKIN high.

<sup>0.5</sup>P = PL, where PL = pulse duration of CLKIN low.



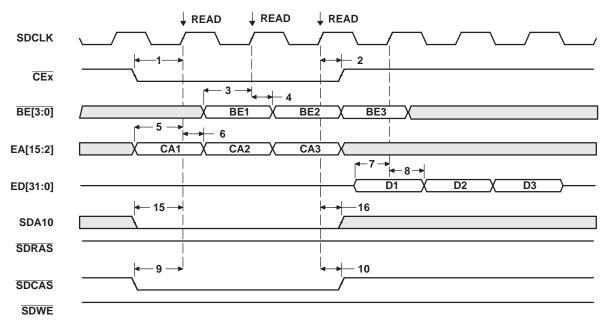


Figure 18. Three SDRAM Read Commands

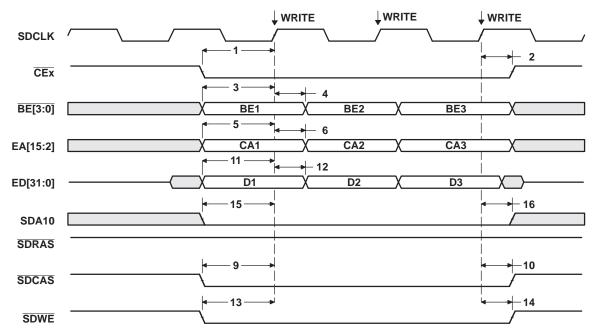


Figure 19. Three SDRAM Write Commands



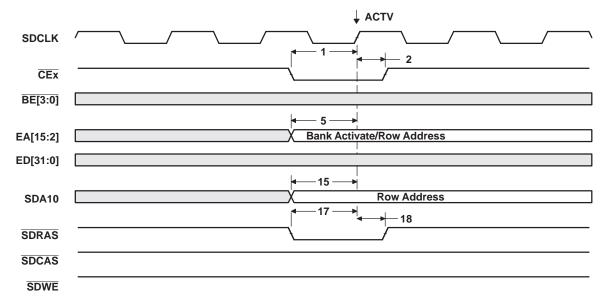


Figure 20. SDRAM ACTV Command

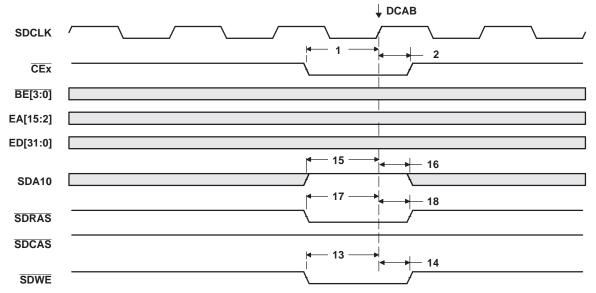


Figure 21. SDRAM DCAB Command



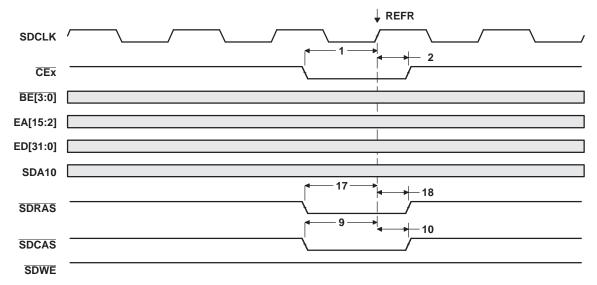


Figure 22. SDRAM REFR Command

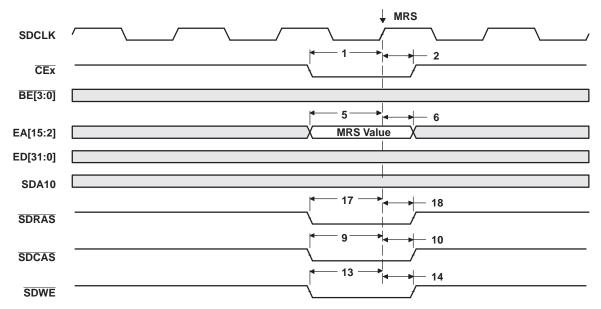


Figure 23. SDRAM MRS Command

### **HOLD/HOLDA TIMING**

## Timing Requirements for the Hold/Hold Acknowledge Cycles<sup>(1)</sup>

(see Figure 24)

NO.			MIN	MAX	UNIT
1	t <sub>su(HOLDH</sub> -CKO1H)	Setup time, HOLD high before CLKOUT1 high	5		ns
2	t <sub>h(CKO1H-HOLDL)</sub>	Hold time, HOLD low after CLKOUT1 high	2		ns

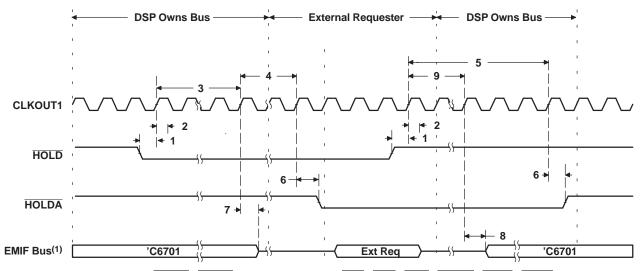
<sup>(1)</sup> HOLD is synchronized internally. Therefore, if setup and hold times are not met, it will either be recognized in the current cycle or in the next cycle. Thus, HOLD can be an asynchronous input.

# Switching Characteristics for the Hold/Hold Acknowledge Cycles<sup>(1)</sup>

(seeFigure 24)

NO.		PARAMETER	MIN	MAX	UNIT
3	t <sub>R(HOLDL-EMHZ)</sub>	Response time, HOLD low to EMIF high impedance	4P		<sup>(2)</sup> ns
4	t <sub>R(EMHZ-HOLDAL)</sub>	Response time, EMIF high impedance to HOLDA low		2P	ns
5	t <sub>R(HOLDH-HOLDAH)</sub>	Response time, HOLD high to HOLDA high	4P	7P	ns
6	t <sub>d(CKO1H-HOLDAL)</sub>	Delay time, CLKOUT1 high to HOLDA valid	1	8	ns
7	t <sub>d(CKO1H-BHZ)</sub>	Delay time, CLKOUT1 high to EMIF Bus high impedance (3)	1 <sup>(4)</sup>	8 <sup>(4)</sup>	ns
8	t <sub>d(CKO1H-BLZ)</sub>	Delay time, CLKOUT1 high to EMIF Bus low impedance (3)	1 <sup>(4)</sup>	12 <sup>(4)</sup>	ns
9	t <sub>R(HOLDH-BLZ)</sub>	Response time, HOLD high to EMIF Bus low impedance (3)	3P	6P	ns

- (1) P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) All pending EMIF transactions are allowed to complete before HOLDA is asserted. The worst cases for this is an asynchronous read or write with external ARDY used or a minimum of eight consecutive SDRAM reads or writes when RBTR8 = 1. If no bus transactions are occurring, then the minimum delay time can be achieved. Also, bus hold can be indefinitely delayed by setting the NOHOLD = 1.
- (3) EMIF Bus consists of CE[3:0], BE[3:0], ED[31:0], EA[21:2], ARE, AOE, AWE, SSADS, SSOE, SSWE, SDA10, SDRAS, SDCAS, and SDWE.
- (4) This parameter is not tested.



(1) EMIF bus consists of CE[3:0], BE[3:0], ED[31:0], EA[21:2], ARE, AOE, AWE, SSADS, SSOE, SSWE, SDA10, SDRAS, SDCAS, and SDWE.

Figure 24. HOLD/HOLDA Timing



#### RESET TIMING

### **Timing Requirements for Reset**

(see Figure 25)

NO.			MIN	MAX	UNIT
1	t <sub>w(RESET)</sub>	Width of the RESET pulse (PLL stable) <sup>(1)</sup>	10 <sup>(2)</sup>		CLKOUT 1 cycles
		Width of the RESET pulse (PLL needs to sync up) (3)	250 <sup>(2)</sup>		μs

- (1) This parameter applies to CLKMODE x1 when CLKIN is stable and applies to CLKMODE x4 when CLKIN and PLL are stable.
- 2) This parameter is not tested.
- (3) This parameter only applies to CLKMODE x4. The RESET signal is not connected internally to the clock PLL circuit. The PLL, however, may need up to 250 µs to stabilize following device powerup or after PLL configuration has been changed. During that time, RESET must be asserted to ensure proper device operation. See the clock PLL section for PLL lock times.

## Switching Characteristics During Reset<sup>(1)</sup>

(see Figure 25)

NO.		PARAMETER	MIN	MAX	UNIT
2	t <sub>R(RESET)</sub>	Response time to change of value in RESET signal	1 <sup>(2)</sup>		CLKOUT1 cycles
3	t <sub>d(CKO1H</sub> -CKO2IV)	Delay time, CLKOUT1 high to CLKOUT2 invalid	-1 <sup>(2)</sup>		ns
4	t <sub>d(CKO1H</sub> -CKO2V)	Delay time, CLKOUT1 high to CLKOUT2 valid		10 <sup>(2)</sup>	ns
5	t <sub>d(CKO1H</sub> -SDCLKIV)	Delay time, CLKOUT1 high to SDCLK invalid	-1 <sup>(2)</sup>		ns
6	t <sub>d(CKO1H</sub> -SDCLKV)	Delay time, CLKOUT1 high to SDCLK valid		10 <sup>(2)</sup>	ns
7	t <sub>d(CKO1H</sub> -SSCKIV)	Delay time, CLKOUT1 high to SSCLK invalid	-1 <sup>(2)</sup>		ns
8	t <sub>d(CKO1H</sub> -SSCKV)	Delay time, CLKOUT1 high to SSCLK valid		10 <sup>(2)</sup>	ns
9	t <sub>d(CKO1H</sub> LOWIV)	Delay time, CLKOUT1 high to low group invalid	-1 <sup>(2)</sup>		ns
10	t <sub>d(CKO1H</sub> LOWV)	Delay time, CLKOUT1 high to low group valid		10 <sup>(2)</sup>	ns
11	t <sub>d(CKO1H</sub> HIGHIV)	Delay time, CLKOUT1 high to high group invalid	-1 <sup>(2)</sup>		ns
12	t <sub>d(CKO1H</sub> HIGHV)	Delay time, CLKOUT1 high to high group valid		10 <sup>(2)</sup>	ns
13	t <sub>d(CKO1H</sub> –zHz)	Delay time, CLKOUT1 high to Z group high impedance	-1 <sup>(2)</sup>		ns
14	t <sub>d(CKO1H-ZV)</sub>	Delay time, CLKOUT1 high to Z group valid		10 <sup>(2)</sup>	ns

<sup>(1)</sup> Low group consists of: IACK, INUM[3:0], DMAC[3:0], PD, TOUT0, and TOUT1. High group consists of: HRDY and HINT.

(2) This parameter is not tested

42

Z group consists of: EA[21:2], ED[31:0], CE[3:0], BE[3:0], ARE, AWE, AOE, SSADS, SSOE, SSWE, SDA10, SDRAS, SDCAS, SDWE, HD[15:0], CLKX0, CLKX1, FSX0, FSX1, DX0, DX1, CLKR0, CLKR1, FSR0, and FSR1.



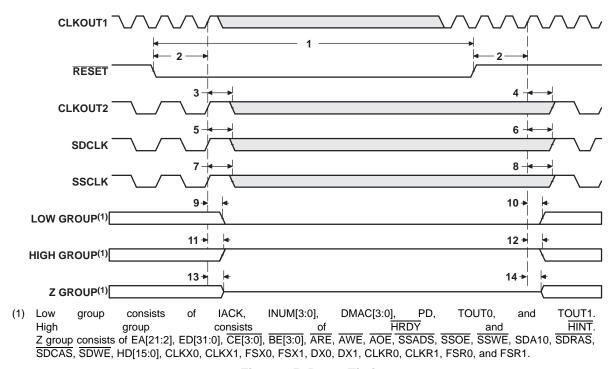


Figure 25. Reset Timing



## **EXTERNAL INTERRUPT/RESET TIMING**

# Timing Requirements for Interrupt Response Cycles (1)(2)

(see Figure 26)

NO.		MIN	MAX	UNIT
2	t <sub>w(ILOW)</sub> Width of the interrupt pulse low	2P <sup>(3)</sup>		ns
3	t <sub>w(IHIGH)</sub> Width of the interrupt pulse high	2P <sup>(3)</sup>		ns

- (1) Interrupt signals are synchronized internally and are potentially recognized one cycle later if setup and hold times are violated. Thus, they can be connected to asynchronous inputs.
- (2) P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (3) This parameter is not tested.

## Switching Characteristics During Interrupt Response Cycles (1)

(see Figure 26)

NO.		PARAMETER	MIN	MAX	UNIT
1	t <sub>R(EINTH-IACKH)</sub>	Response time, EXT_INTx high to IACK high	9P		ns
4	t <sub>d(CKO2L-IACKV)</sub>	Delay time, CLKOUT2 low to IACK valid	-0.5P	13 – 0.5P	ns
5	t <sub>d(CKO2L</sub> INUMV)	Delay time, CLKOUT2 low to INUMx valid		10 – 0.5P	ns
6	t <sub>d(CKO2L-INUMIV)</sub>	Delay time, CLKOUT2 low to INUMx invalid	-0.5P		ns

(1) P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns. When the PLL is used (CLKMODE x4), 0.5P = 1/(2 x CPU clock frequency). For CLKMODE x1: 0.5P = PH, where PH is the high period of CLKIN.

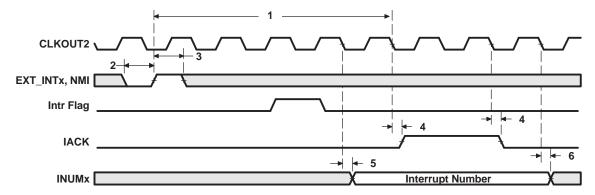


Figure 26. Interrupt Timing

Submit Documentation Feedback

#### **HOST-PORT INTERFACE TIMING**

# Timing Requirements for Host-Port Interface Cycles (1)(2)

(see Figure 27, Figure 28, Figure 29, and Figure 30)

NO.			MIN	MAX	UNIT
1	t <sub>su(SEL-HSTBL)</sub>	Setup time, select signals (3) valid before HSTROBE low	4		ns
2	t <sub>h(HSTBL-SEL)</sub>	Hold time, select signals <sup>(3)</sup> valid after HSTROBE low	2		ns
3	t <sub>w(HSTBL)</sub>	Pulse duration, HSTROBE low	2P <sup>(4)</sup>		ns
4	t <sub>w(HSTBH)</sub>	Pulse duration, HSTROBE high between consecutive accesses	2P <sup>(4)</sup>		ns
10	t <sub>su(SEL-HASL)</sub>	Setup time, select signals (3) valid before HAS low	4		ns
11	t <sub>h(HASL-SEL)</sub>	Hold time, select signals <sup>(3)</sup> valid after HAS low	2		ns
12	t <sub>su(HDV-HSTBH)</sub>	Setup time, host data valid before HSTROBE high	3		ns
13	t <sub>h(HSTBH-HDV)</sub>	Hold time, host data valid after HSTROBE high	2		ns
14	t <sub>h(HRDYL-HSTBL)</sub>	Hold time, HSTROBE low after HRDY low. HSTROBE should not be inactivated until HRDY is active (low); otherwise, HPI writes will not complete properly.	1 (4)		ns
18	t <sub>su(HASL-HSTBL)</sub>	Setup time, HAS low before HSTROBE low	2 <sup>(4)</sup>		ns
19	t <sub>h(HSTBL-HASL)</sub>	Hold time, HAS low after HSTROBE low	2 <sup>(4)</sup>		ns

- HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.
- The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- Select signals include: HCNTRL[1:0], HR/W, and HHWIL.
- This parameter is not tested.

## Switching Characteristics During Host-Port Interface Cycles (1)(2)

(see Figure 27, Figure 28, Figure 29, and Figure 30)

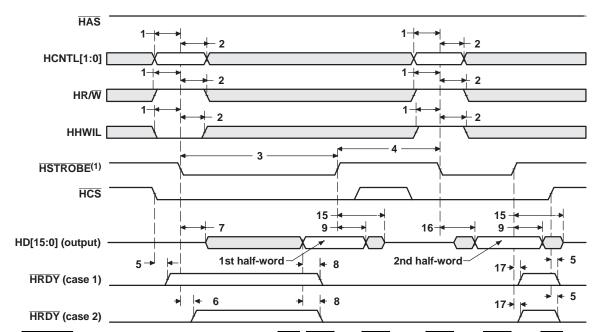
NO.		PARAMETER	MIN	MAX	UNIT
5	t <sub>d(HCS-HRDY)</sub>	Delay time, HCS to HRDY (3)	1	12	ns
6	t <sub>d(HSTBL-HRDYH)</sub>	Delay time, HSTROBE low to HRDY high (4)	1	12	ns
7	toh(HSTBL-HDLZ)	Output hold time, HD low impedance after HSTROBE low for an HPI read	4 <sup>(5)</sup>		ns
8	t <sub>d(HDV-HRDYL)</sub>	Delay time, HD valid to HRDY low	P - 3 <sup>(5)</sup>	P + 3 <sup>(5)</sup>	ns
9	t <sub>oh(HSTBH-HDV)</sub>	Output hold time, HD valid after HSTROBE high	3	12	ns
15	t <sub>d(HSTBH</sub> HDHZ)	Delay time, HSTROBE high to HD high impedance	3 <sup>(5)</sup>	12 <sup>(5)</sup>	ns
16	t <sub>d(HSTBL-HDV)</sub>	Delay time, HSTROBE low to HD valid	3	12	ns
17	t <sub>d(HSTBH-HRDYH)</sub>	Delay time, HSTROBE high to HRDY high (6)	1	12	ns

- HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.
- The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

  HCS enables HRDY, and HRDY is always low when HCS is high. The case where HRDY goes high when HCS falls indicates that HPI
- is busy completing a previous HPID write or READ with autoincrement.
- This parameter is used during an HPID read. At the beginning of the first half-word transfer on the falling edge of HSTROBE, the HPI sends the request to the DMA auxiliary channel, and HRDY remains high until the DMA auxiliary channel loads the requested data into HPID.
- This parameter is not tested.
- This parameter is used after the second half-word of an HPID write or autoincrement read. HRDY remains low if the access is not an HPID write or autoincrement read. Reading or writing to HPIC or HPIA does not affect the HRDY signal.

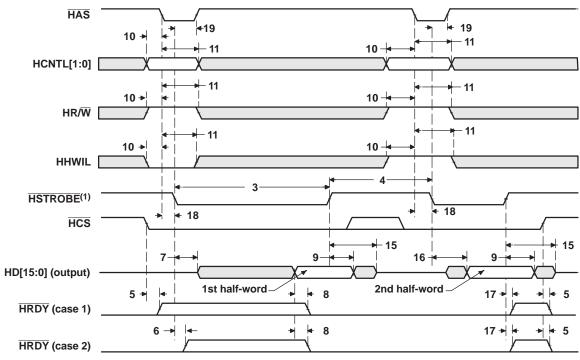
Copyright © 2000-2009, Texas Instruments Incorporated





(1) HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

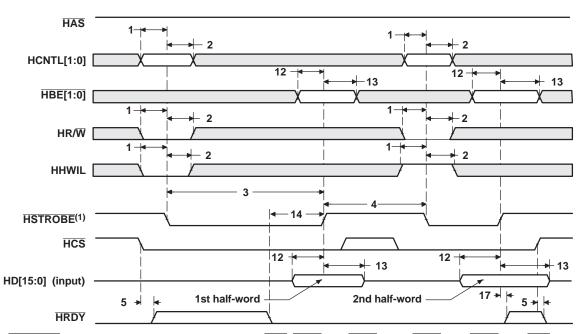
Figure 27. HPI Read Timing (HAS Not Used, Tied High)



(1) HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

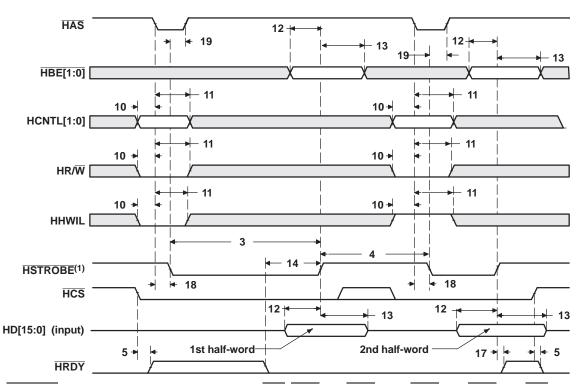
Figure 28. HPI Read Timing (HAS Used)





(1)  $\overline{\text{HSTROBE}}$  refers to the following logical operation on  $\overline{\text{HCS}}$ ,  $\overline{\text{HDS1}}$ , and  $\overline{\text{HDS2}}$ : [NOT( $\overline{\text{HDS1}}$  XOR  $\overline{\text{HDS2}}$ )] OR  $\overline{\text{HCS}}$ .

Figure 29. HPI Write Timing (HAS Not Used, Tied High)



(1)  $\overline{\text{HSTROBE}}$  refers to the following logical operation on  $\overline{\text{HCS}}$ ,  $\overline{\text{HDS1}}$ , and  $\overline{\text{HDS2}}$ : [NOT( $\overline{\text{HDS1}}$  XOR  $\overline{\text{HDS2}}$ )] OR  $\overline{\text{HCS}}$ .

Figure 30. HPI Write Timing (HAS Used)



### **MULTICHANNEL BUFFERED SERIAL PORT TIMING**

# Timing Requirements for McBSP<sup>(1)(2)</sup>

(see Figure 31)

NO.				MIN	MAX	UNIT
2	t <sub>c(CKRX)</sub>	Cycle time, CLKR/X	CLKR/X ext	2P <sup>(3)</sup>		ns
3	t <sub>w(CKRX)</sub>	Pulse duration, CLKR/X high or CLKR/X low	CLKR/X ext	P – 1 <sup>(3)</sup>		ns
5	4	Satura time, external ESP high before CLVP law	CLKR int	13 <sup>(3)</sup>		ns
Э	t <sub>su(FRH-CKRL)</sub> Setup time, external FSR high before CLKR low	CLKR ext	4		ns	
6	t <sub>h(CKRL-FRH)</sub> Hold time, external FSR high after CLKR low	Lold time outernal FCD high offer CLVD law	CLKR int	7 <sup>(3)</sup>		20
0		CLKR ext	4		ns	
7	t <sub>su(DRV-CKRL)</sub> Setup time, DR valid before CLKR low	t Catura times DD walled history CLVD law.	CLKR int	10		
1		CLKR ext	1		ns	
0		Held time DD valid after CLVD law.	CLKR int	4		
8	t <sub>h</sub> (CKRL-DRV)	Hold time, DR valid after CLKR low	CLKR ext	4		ns
40		Catura times automas I FCV high hafers CLIVV lavo	CLKX int	13 <sup>(3)</sup>		
10	t <sub>su(FXH</sub> -CKXL)	Setup time, external FSX high before CLKX low	CLKX ext	4		ns
11		Lold time outernal FCV high ofter CLIVV law	CLKX int	7 <sup>(3)</sup>		
11	<sup>t</sup> h(CKXL-FXH)	Hold time, external FSX high after CLKX low	CLKX ext	3		ns

<sup>(1)</sup> P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

<sup>(2)</sup> CLKRP = CLKXP = FSRP = FSXP = 0 in the pin control register (PCR). If polarity of any of the signals is inverted, then the timing references of that signal are also inverted.

<sup>(3)</sup> This parameter is not tested.

# Switching Characteristics for McBSP<sup>(1)(2)(3)</sup>

(see Figure 31)

NO.		PARAMETER			MAX	UNIT
1	t <sub>d</sub> (CKSH-CKRXH)	Delay time, CLKS high to CLKR/X high for internal CLKR/X generated from CLKS input		3	15	ns
2	t <sub>c(CKRX)</sub>	Cycle time, CLKR/X	CLKR/X int	2P		ns
3	t <sub>w(CKRX)</sub>	Pulse duration, CLKR/X high or CLKR/X low	CLKR/X int	C - 1 <sup>(4)</sup>	C + 1 <sup>(4)</sup>	ns
4	t <sub>d(CKRH</sub> FRV)	Delay time, CLKR high to internal FSR valid	CLKR int	-4	4	ns
0	t <sub>d(CKXH–FXV)</sub> Delay time, CLKX high to internal FSX valid	CLKX int	-4	5	20	
9		CLKX ext	3 <sup>(5)</sup>	16 <sup>(5)</sup>	ns	
40		Disable time, DX high impedance following last data bit	CLKX int	-3 <sup>(5)</sup>	2 <sup>(5)</sup>	
12	t <sub>dis</sub> (CKXH–DXHZ)	from CLKX high	CLKX ext	2 <sup>(5)</sup>	9 <sup>(5)</sup>	ns
40		Deleviting OHVV high to DV collid	CLKX int	-2	4	
13	<sup>t</sup> d(CKXH–DXV)	t <sub>d(CKXH-DXV)</sub> Delay time, CLKX high to DX valid.	CLKX ext	3	16	ns
		Delay time, FSX high to DX valid.	FSX int	-2 <sup>(5)</sup>	4 <sup>(5)</sup>	
14	14 t <sub>d(FXH-DXV)</sub>	ONLY applies when in data delay 0 (XDATDLY = 00b) mode.	FSX ext	2 <sup>(5)</sup>	10 <sup>(5)</sup>	ns

CLKRP = CLKXP = FSRP = FSXP = 0 in the pin control register (PCR). If polarity of any of the signals is inverted, then the timing references of that signal are also inverted.

Minimum delay times also represent minimum output hold times.

P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

C = H or L

S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency) = sample rate generator input clock = P\_clks if CLKSM = 0 (P\_clks = CLKS period) H = CLKX high pulse width = (CLKGDV/2 + 1) \* S if CLKGDV is even

<sup>=</sup> (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero L = CLKX low pulse width = (CLKGDV/2) \* S if CLKGDV is even

<sup>= (</sup>CLKGDV + 1)/2 \* S if CLKGDV is odd or zero

<sup>(5)</sup> This parameter is not tested.



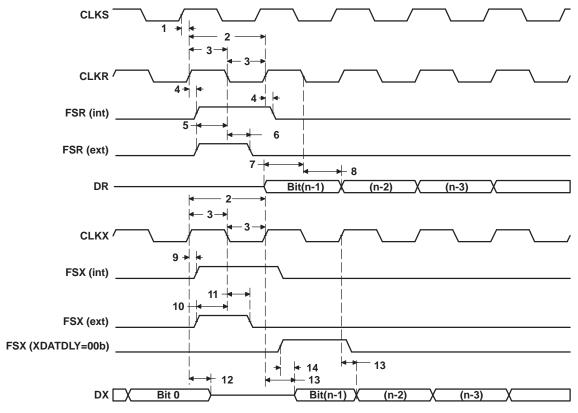


Figure 31. McBSP Timing

## Timing Requirements for FSR When GSYNC = 1

(see Figure 32)

NO.			MIN	MAX	UNIT
1	tsu(FRH-CKSH)	Setup time, FSR high before CLKS high	4 <sup>(1)</sup>		ns
2	th(CKSH-FRH)	Hold time, FSR high after CLKS high	4 <sup>(1)</sup>		ns

#### (1) This parameter is not tested.

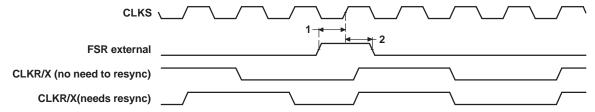


Figure 32. FSR Timing When GSYNC = 1

# Timing Requirements for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = $0^{(1)(2)}$

(seeFigure 33)

NO.			MASTE	MASTER		SLAVE	
NO.			MIN	MAX	MIN	MAX	UNIT
4	t <sub>su(DRV-CKXL)</sub>	Setup time, DR valid before CLKX low	12		2 – 3P		ns
5	t <sub>h(CKXL-DRV)</sub>	Hold time, DR valid after CLKX low	4		5 + 6P		ns

- 1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.

# Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 10b, $CLKXP=0^{(1)(2)}$ (see Figure 33)

NO.		PARAMETER		MASTER (3)		SLAVE	
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT
1	t <sub>h(CKXL-FXL)</sub>	Hold time, FSX low after CLKX low <sup>(4)</sup>	T – 4	T + 4			ns
2	t <sub>d(FXL-CKXH)</sub>	Delay time, FSX low to CLKX high (5)	L – 4	L+4			ns
3	t <sub>d(CKXH-DXV)</sub>	Delay time, CLKX high to DX valid	-4	4	3P + 1	5P + 17	ns
6	t <sub>dis(CKXL-DXHZ)</sub>	Disable time, DX high impedance following last data = bit from CLKX low	L - 2 <sup>(6)</sup>	L + 3 <sup>(6)</sup>			ns
7	t <sub>dis(FXH-DXHZ)</sub>	Disable time, DX high impedance following last data = bit from FSX high			P + 4 <sup>(6)</sup>	3P + 17 <sup>(6)</sup>	ns
8	t <sub>d(FXL-DXV)</sub>	Delay time, FSX low to DX valid			2P + 1	4P + 13	ns

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- (3) S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
  - = sample rate generator input clock = P\_clks if CLKSM = 0 (P\_clks = CLKS period)
  - T = CLKX period = (1 + CLKGDV) \* S
  - H = CLKX high pulse width = (CLKGDV/2 + 1) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
  - L = CLKX low pulse width = (CLKGDV/2) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
- (4) FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally.
  - CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP
  - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- (5) FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- (6) This parameter is not tested.

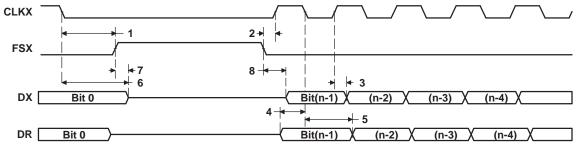


Figure 33. McBSP Timing as SPI Master or Slave: CLKSTP = 10b, CLKXP = 0

# Timing Requirements SPI Master or Slave: CLKSTP = 11b, CLKXP = 0<sup>(1)(1)</sup>

(see Figure 34)

(1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.



## Timing Requirements SPI Master or Slave: CLKSTP = 11b, CLKXP = 0 (continued)

(see Figure 34)

NO.			MASTI	MASTER		SLAVE		
NO.			MIN	MAX	MIN	MAX	UNIT	
4	t <sub>su(DRV-CKXH)</sub>	Setup time, DR valid before CLKX high	12		2 – 3P		ns	
5	t <sub>h(CKXH-DRV)</sub>	Hold time, DR valid after CLKX high	4		5 + 6P		ns	

# Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = $0^{(1)(2)}$ (see Figure 34)

NO.		PARAMETER		MASTER <sup>(3)</sup>		SLAVE		
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT	
1	t <sub>h(CKXL-FXL)</sub>	Hold time, FSX low after CLKX low (4)	L – 4	L + 4			ns	
2	t <sub>d(FXL-CKXH)</sub>	Delay time, FSX low to CLKX high (5)	T – 4	T + 4			ns	
3	t <sub>d(CKXL-DXV)</sub>	Delay time, CLKX low to DX valid	-4	4	3P + 1	5P + 17	ns	
6	t <sub>dis(CKXL-DXHZ)</sub>	Disable time, DX high impedance following last data bit from CLKX low	-2 <sup>(6)</sup>	4 <sup>(6)</sup>	3P + 4 <sup>(6)</sup>	5P + 17 <sup>(6)</sup>	ns	
7	t <sub>d(FXL-DXV)</sub>	Delay time, FSX low to DX valid	$H - 2^{(6)}$	H + 3 <sup>(6)</sup>	2P + 1	4P + 13	ns	

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- 3) S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
  - = sample rate generator input clock = P\_clks if CLKSM = 0 (P\_clks = CLKS period)
  - T = CLKX period = (1 + CLKGDV) \* S
  - H = CLKX high pulse width = (CLKGDV/2 + 1) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
  - L = CLKX low pulse width = (CLKGDV/2) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
- (4) FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally.
  - CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP
  - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- (5) FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- (6) This parameter is not tested.

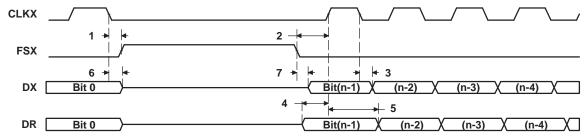


Figure 34. McBSP Timing as SPI Master or Slave: CLKSTP = 11b, CLKXP = 0

52

# Timing Requirements for MCBSP as SPI Master or Slave: CLKSTOP = 10b, CLKXP = 1<sup>(1)(2)</sup>

(see Figure 35)

NO.			MASTI	MASTER		SLAVE		
NO.			MIN	MAX	MIN	MAX	UNIT	
4	t <sub>su(DRV-CKXH)</sub>	Setup time, DR valid before CLKX high	12		2 – 3P		ns	
5	t <sub>h(CKXH-DRV)</sub>	Hold time, DR valid after CLKX high	4		5 + 6P		ns	

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.

# Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = 1<sup>(1)(2)</sup> (see Figure 35)

NO.		PARAMETER		MASTER <sup>(3)</sup>		SLAVE	
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT
1	t <sub>h(CKXH-FXL)</sub>	Hold time, FSX low after CLKX high (4)	T – 4	T + 4			ns
2	t <sub>d(FXL-CKXL)</sub>	Delay time, FSX low to CLKX low <sup>(5)</sup>	H – 4	H + 4			ns
3	t <sub>d(CKXL-DXV)</sub>	Delay time, CLKX low to DX valid	-4	4	3P + 1	5P + 17	ns
6	t <sub>dis(CKXH-DXHZ)</sub>	Disable time, DX high impedance following last data bit from CLKX high	H – 2 <sup>(6)</sup>	H + 3 <sup>(6)</sup>			ns
7	t <sub>dis(FXH-DXHZ)</sub>	Disable time, DX high impedance following last data bit from FSX high			P + 4 <sup>(6)</sup>	3P + 17 <sup>(6)</sup>	ns
8	t <sub>d(FXL-DXV)</sub>	Delay time, FSX low to DX valid			2P + 1	4P + 13	ns

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- (3) S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
  - = sample rate generator input clock = P\_clks if CLKSM = 0 (P\_clks = CLKS period)
  - T = CLKX period = (1 + CLKGDV) \* S
  - H = CLKX high pulse width = (CLKGDV/2 + 1) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
  - L = CLKX low pulse width = (CLKGDV/2) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
- (4) FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally.
  - CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP
  - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- (5) FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- (6) This parameter is not tested.

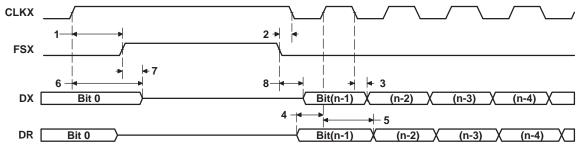


Figure 35. McBSP Timing as SPI Master or Slave: CLKSTP = 10b, CLKXP = 1

# Timing Requirements for McBSP as SPI Master or Slave: CLKSTOP = 11b, CLKXP = 1<sup>(1)(2)</sup> (see Figure 36)

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.



# Timing Requirements for McBSP as SPI Master or Slave: CLKSTOP = 11b, CLKXP = 1 (continued)

(see Figure 36)

NO			MASTE	MASTER		SLAVE	
NO.			MIN	MAX	MIN	MAX	UNIT
4	t <sub>su(DRV-CKXL)</sub>	Setup time, DR valid before CLKX low	12		2 - 3P		ns
5	t <sub>h(CKXL-DRV)</sub>	Hold time, DR valid after CLKX low	4		5 + 6P		ns

# Switching Characteristics for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = 1<sup>(1)(2)</sup> (see Figure 36)

NO.		PARAMETER		MASTER (3)		SLAVE		
NO.		PARAMETER	MIN	MAX	MIN	MAX	UNIT	
1	t <sub>h(CKXH-FXL)</sub>	Hold time, FSX low after CLKX high (4)	H – 4	H + 4			ns	
2	t <sub>d(FXL-CKXL)</sub>	Delay time, FSX low to CLKX low <sup>(5)</sup>	T – 4	T + 4			ns	
3	t <sub>d(CKXH-DXV)</sub>	Delay time, CLKX high to DX valid	-4	4	3P + 1	5P + 17	ns	
6	t <sub>dis(CKXH-DXHZ)</sub>	Disable time, DX high impedance following last data bit from CLKX high	-2 <sup>(6)</sup>	4 <sup>(6)</sup>	3P + 4 <sup>(6)</sup>	5P + 17 <sup>(6)</sup>	ns	
7	t <sub>d(FXL-DXV)</sub>	Delay time, FSX low to DX valid	L – 2 <sup>(6)</sup>	L + 3 <sup>(6)</sup>	2P + 1	4P + 13	ns	

- (1) The effects of internal clock jitter are included at test. There is no need to adjust timing numbers for internal clock jitter. P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.
- (2) For all SPI slave modes, CLKG is programmed as 1/2 of the CPU clock by setting CLKSM = CLKGDV = 1.
- (3) S = sample rate generator input clock = P if CLKSM = 1 (P = 1/CPU clock frequency)
  - = sample rate generator input clock = P\_clks if CLKSM = 0 (P\_clks = CLKS period)
  - T = CLKX period = (1 + CLKGDV) \* S
  - H = CLKX high pulse width = (CLKGDV/2 + 1) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
  - L = CLKX low pulse width = (CLKGDV/2) \* S if CLKGDV is even
  - = (CLKGDV + 1)/2 \* S if CLKGDV is odd or zero
- (4) FSRP = FSXP = 1. As a SPI master, FSX is inverted to provide active-low slave-enable output. As a slave, the active-low signal input on FSX and FSR is inverted before being used internally.
  - CLKXM = FSXM = 1, CLKRM = FSRM = 0 for master McBSP
  - CLKXM = CLKRM = FSXM = FSRM = 0 for slave McBSP
- (5) FSX should be low before the rising edge of clock to enable slave devices and then begin a SPI transfer at the rising edge of the master clock (CLKX).
- (6) This parameter is not tested.

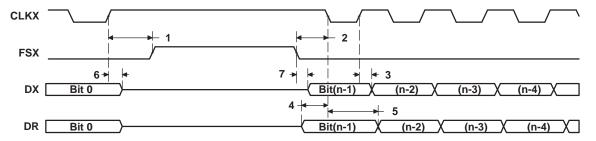


Figure 36. McBSP Timing as SPI Master or Slave: CLKSTP = 11b, CLKXP = 1

Submit Documentation Feedback

### DMAC, TIMER, POWER-DOWN TIMING

## **Switching Characteristics for DMAC Outputs**

(see Figure 37)

NO.	PARAMETER	MIN	MAX	UNIT
1	t <sub>d(CKO1H-DMACV)</sub> Delay time, CLKOUT1 high to DMAC valid	2	11	ns

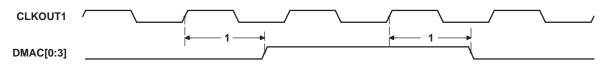


Figure 37. DMAC Timing

# Timing Requirements for Timer Inputs<sup>(1)</sup>

(see Figure 38)

NO.			MIN	MAX	UNIT
1	t <sub>w(TINPH)</sub>	Pulse duration, TINP high	2P		ns

<sup>(1)</sup> P = 1/CPU clock frequency in ns. For example, when running parts at 140 MHz, use P = 7 ns.

## **Switching Characteristics for Timer Outputs**

(see Figure 38)

NO.		PARAMETER	MIN	MAX	UNIT
2	t <sub>d</sub> (CKO1H-TOUTV)	Delay time, CLKOUT1 high to TOUT valid		1 10	ns

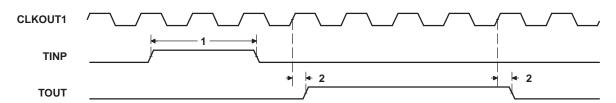


Figure 38. Timer Timing

## **Switching Characteristics for Power-Down Outputs**

(seeFigure 39)

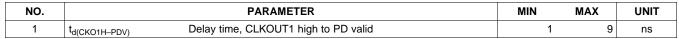




Figure 39. Power-Down Timing

## **JTAG TEST-PORT TIMING**

## **Timing Requirements for JTAG Test Port**

(see Figure 40)

Copyright © 2000–2009, Texas Instruments Incorporated



# Timing Requirements for JTAG Test Port (continued)

(see Figure 40)

NO.			MIN	MAX	UNIT
1	t <sub>c(TCK)</sub>	Cycle time, TCK	35		ns
3	t <sub>su(TDIV</sub> -TCKH)	Setup time, TDI/TMS/TRST valid before TCK high	10		ns
4	t <sub>h(TCKH</sub> TDIV)	Hold time, TDI/TMS/TRST valid after TCK high	9		ns

# **Switching Characteristics for JTAG Test Port**

(see Figure 40)

NO.	PARAMETER	MIN	MAX	UNIT
2	t <sub>d(TCKL-TDOV)</sub> Delay time, TCK low to TDO valid	-3 <sup>(1)</sup>	15 <sup>(1)</sup>	ns

(1) This parameter is not tested.

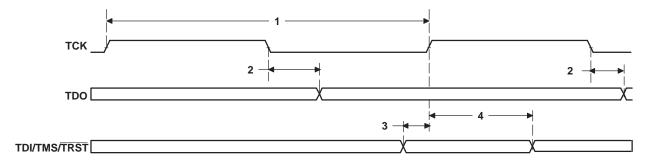


Figure 40. JTAG Test-Port Timing

#### PACKAGE OPTION ADDENDUM

www.ti.com 30-Jul-2009

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9866101VXA	ACTIVE	CFCBGA	GLP	429	1	TBD	Call TI	N / A for Pkg Type
5962-9866102VXA	ACTIVE	CFCBGA	GLP	429	1	TBD	Call TI	N / A for Pkg Type
5962-9866102VYC	ACTIVE	FCLGA	ZMB	429	1	TBD	Call TI	N / A for Pkg Type

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SMJ320C6701-SP:

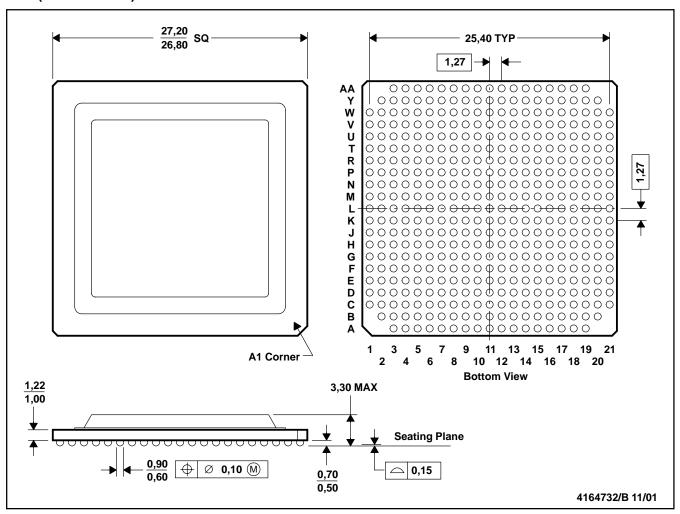
Catalog: SMJ320C6701

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

### GLP (S-CBGA-N429)

#### **CERAMIC BALL GRID ARRAY**

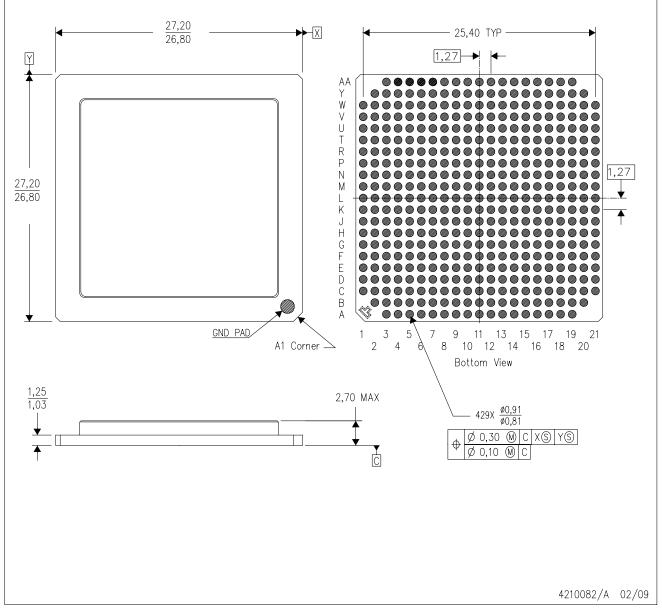


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-156
- D. Flip chip application only

# ZMB (S-CLGA-N429)

## CERAMIC LAND GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Flip chip application only.
- D. All Ball Pads are Gold plated.



#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications			
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio		
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive		
DLP® Products	www.dlp.com	Communications and Telecom	www.ti.com/communications		
DSP	<u>dsp.ti.com</u>	Computers and Peripherals	www.ti.com/computers		
Clocks and Timers	www.ti.com/clocks	Consumer Electronics	www.ti.com/consumer-apps		
Interface	interface.ti.com	Energy	www.ti.com/energy		
Logic	logic.ti.com	Industrial	www.ti.com/industrial		
Power Mgmt	power.ti.com	Medical	www.ti.com/medical		
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security		
RFID	www.ti-rfid.com	Space, Avionics & Defense	www.ti.com/space-avionics-defense		
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video and Imaging	www.ti.com/video		
		Wireless	www.ti.com/wireless-apps		